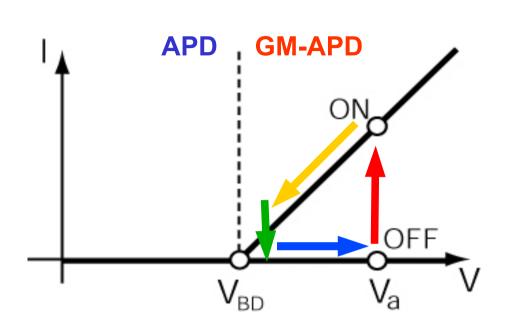
# Review of timing measurements with Silicon Photo-multipliers

<u>G.Collazuol</u>, Scuola Normale Superiore and INFN - Pisa on behalf of the DASIPM collaboration

#### Overview

- Introduction
- Review of intrinsic SiPM timing
- Qualitative comparison with RPL model
- Examples of electronics for timing and of timing applications
- Conclusions
- Appendix: SiPM properties at different temperatures

## Operation principle of a GM-APD



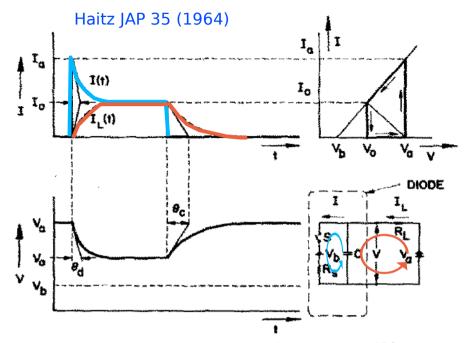
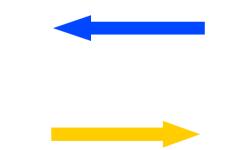


Fig. 3. Shape of current pulse for  $\theta_d \ll r_1(I_0)$ .

OFF condition: avalanche quenched, switch open, capacitance charged until no current flowing from  $V_{BD}$  to  $V_{BIAS}$  with time constant  $R_q x C_D = \tau_{Quenching}$  ( $\rightarrow$  recovery time)

P<sub>01</sub> = turn-on probability probability that a carrier traversing the high-field region triggers the avalanche

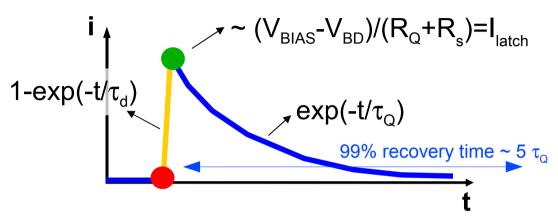


P<sub>10</sub> = turn-off probability probability that the number of carriers traversing the high-field region fluctuates to 0

ON condition: avalanche triggered, switch closed  $C_D$  discharges to  $V_{BD}$  with a time constant  $R_S x C_D = \tau_{discharge}$ , at the same time the external current asymptotic grows to  $(V_{BIAS} - V_{BD})/(R_O + R_S)$ 

# Operation principle of a GM-APD

If  $R_Q$  is high enough the internal current is so low that statistical fluctuations may quench the avalanche



The leading hedge of the signal is much faster than trailing edge:

- 1.  $\tau_d = R_S \cdot C_D << R_Q \cdot C_D = \tau_Q$
- 2. turn-off mean time is very short (if  $R_{Q is}$  sufficiently high,  $I_{latch} \sim 10 \mu A$ )

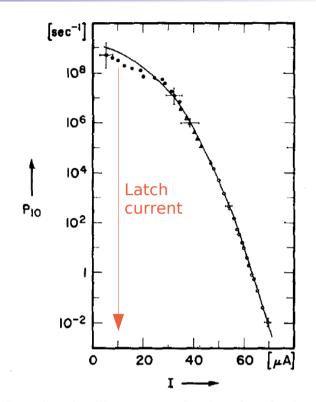


Fig. 2. Turnoff probability per second as function of pulse current.

Haitz |AP 35 (1964)

The charge collected per event is the area under the exponential which is determined by circuital elements and bias.

It is possible to define a GAIN (discharge of a capacitor !!!)

$$\mathbf{G} = \frac{\mathbf{I}_{\text{max}} \cdot \boldsymbol{\tau}_{\text{Q}}}{\mathbf{q}_{\text{e}}} = \frac{(\mathbf{V}_{\text{bias}} - \mathbf{V}_{\text{BD}}) \cdot \boldsymbol{\tau}_{\text{Q}}}{(\mathbf{R}_{\text{Q}} + \mathbf{R}_{\text{S}}) \cdot \mathbf{q}_{\text{e}}} = \frac{(\mathbf{V}_{\text{bias}} - \mathbf{V}_{\text{BD}}) \cdot \mathbf{C}_{\text{D}}}{\mathbf{q}_{\text{e}}}$$

Gain fluctuations in GM-APD are smaller than in APD because electrons and holes give the same signal !!!

# GM-APD timing: fast and slow components

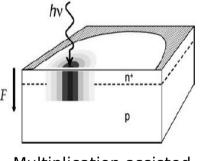
1) Fast component: gaussian with time scale O(10ps)

Statistical fluctuations in the avalanche:

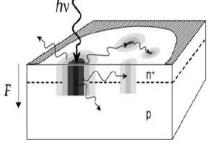
- Longitudinal build-up (minor contribution)
- Transversal propagation (main contribution):
  - via Multiplication assisted diffusion (dominating)

A.Lacaita et al. APL and El.Lett. 1990

via Photon assisted propagation
 PP.Webb, R.J. McIntyre RCA Eng. 1982
 A.Lacaita et al. APL 1992



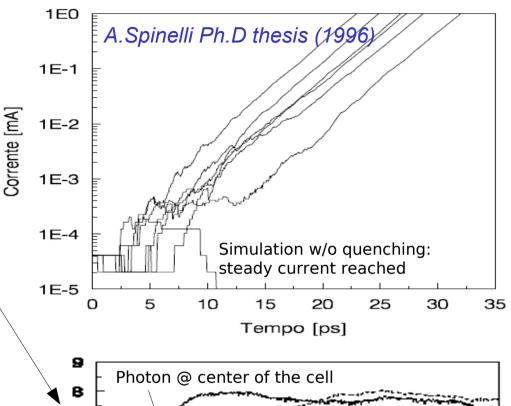
Multiplication assisted diffusion

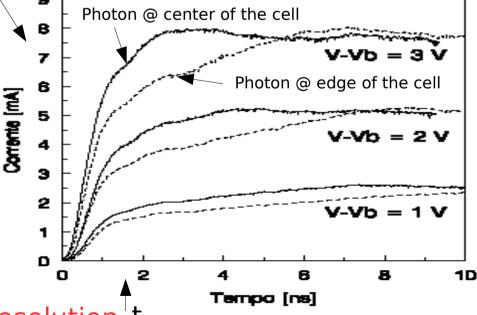


Photon assisted propagation



Dependence of avalanche build-up rate on the impact position ( $\rightarrow$  cell size)





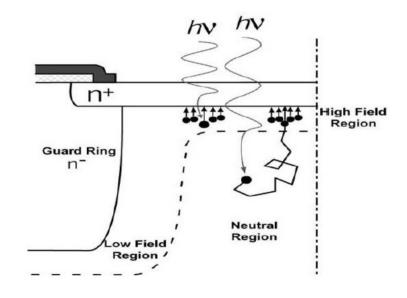
Higher overvoltage → improved time resolution t₁

## GM-APD timing: fast and slow components

2) Slow component: minor non gaussian tails with time scale O(ns)

Carriers photogenerated in the neutral regions beneath the junction and reaching the electric field region by diffusion

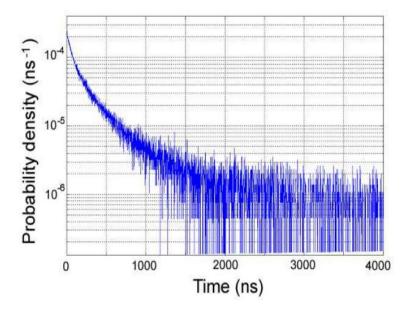
G.Ripamonti, S.Cova Sol.State Electronics (1985)



tail lifetime:  $\tau \sim L^2 / \pi^2 D$ 

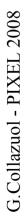
L = effective neutral layer thickness

D = diffusion coefficient



S.Cova et al. NIST Workshop on SPD (2003)

Shorter wavelengths → higher resolution (less tails)



# Single photon time resolution: measurement

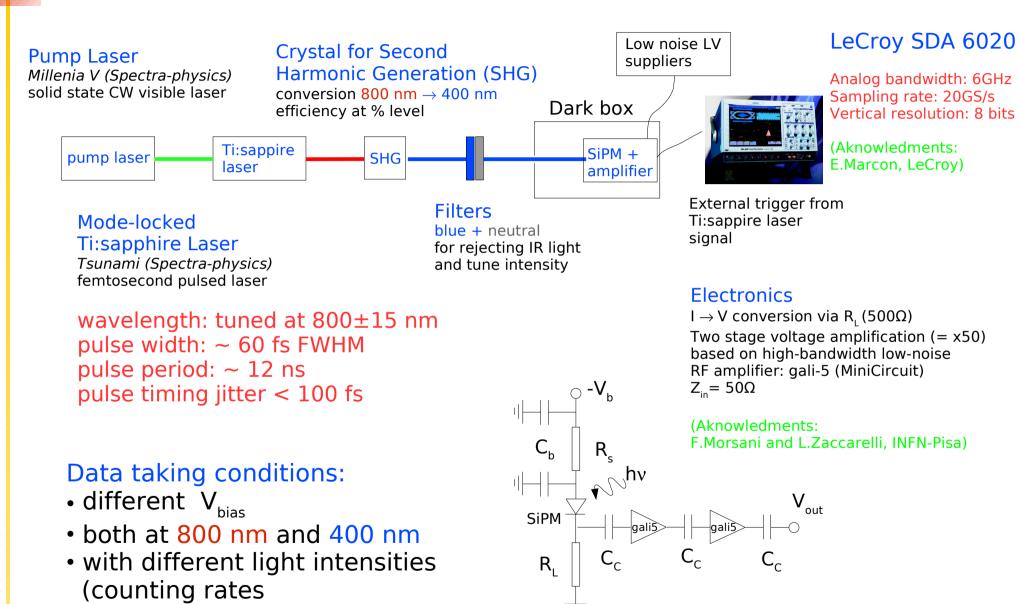
## **Experimental Method**

- SiPM exposed to pulsed femto-second laser in low light intensity conditions (single photon)
- SiPM signal is sampled at high rate and the time of the pulses measured by waveform analysis
- Time resolution measured by studying the distribution of time differences between successive pulses (from the same SiPM)
- Samples: FBK-IRST, Hamamatsu (HPK), CPTA/Photonique

## **Experimental Setup**

in the range 10÷20 Mhz

ie 15÷30 KHz per single cell)

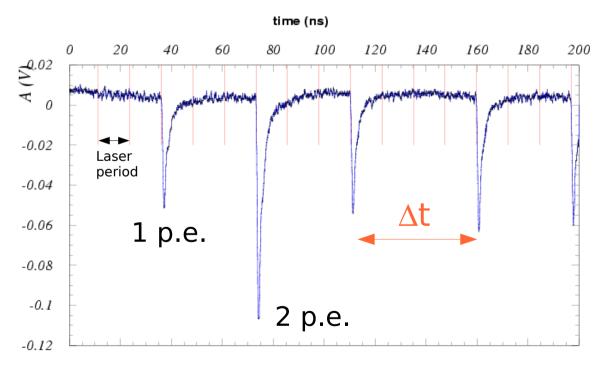


**GND** 

## Waveform analysis: method

- (1) Selection of candidate peaks:
- single photon peaks
- proper signal shape
- low instantaneous intensity (no activity before/after within 50ns)
- low noise during the previous 10 ns (typical noise ~ 1mV rms)

- (2) Peak reconstruction
- optimum time reconstruction
- amplitude and width (baseline shift correction)
- (3) Time difference ∆t between consecutive peaks

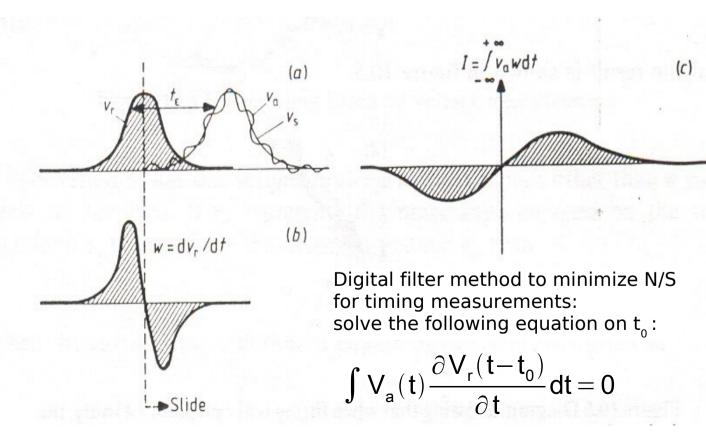


NOTE: working fine at 20MHz counting rate

### Waveform analysis: time reconstruction

Different methods to reconstruct the time of a peak:

- x parabolic fit to find the peak maximum
- x average of time samples weighted by the waveform derivative
- ✓ digital filter: weighting by the derivative of a reference signal
  - → best against noise (signal shape known)



Va = measured signal (includes noise) Vr = reference signal t<sub>o</sub> = reference time

# Single Photon Timing Resolution (SPTR)

Analysis of the distributions of the t difference between successive peaks (modulo the laser period  $T_{laser}$ =12.367ns)

Data at  $\lambda$ =400nm fit gives reasonable  $\chi^2$  with gaussian ( $\sigma_t^{fit}$ ) + constant term (dark noise contribution)

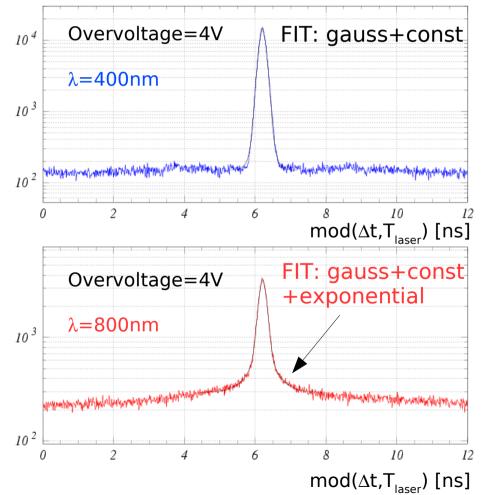
The detector resolution is obtained by  $\sigma_{\!_{\scriptscriptstyle +}}^{\rm \, fit}/\!\sqrt{2}$ 

Data at  $\lambda=800$ nm fit gives reasonable  $\chi^2$  with an additional exponential term  $\exp(-\Delta t/\tau)$ 

- $\tau \sim 0.2 \div 0.8$ ns in rough agreement with diffusion tail lifetime:  $\tau \sim L^2/\pi^2 \, D$  if L is taken to be the diffusion length
- Contribution from the tails ~ 10÷30% of the resolution function area

Gaussian + rms~50-100 ps

Tails (long  $\lambda$ ) ~ exp (-t / O(ns)) contrib. several % for long wavelengths



# **Systematics**

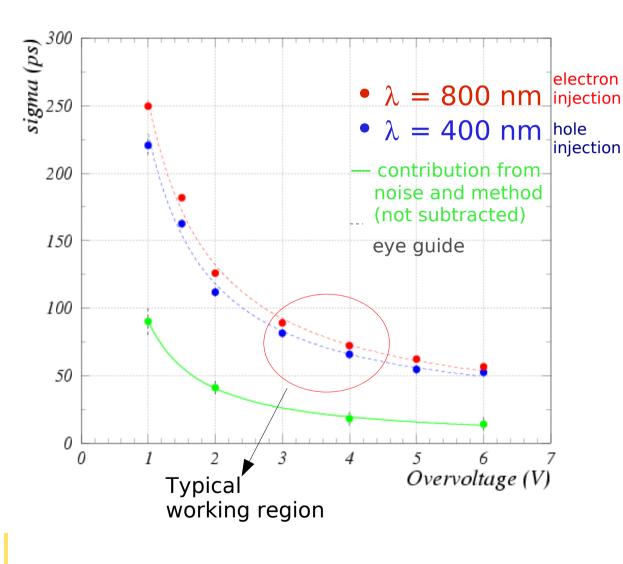
- Contribution (main) form the electronic noise:
  - (1) directly measured by splitting in two the signal of the SiPM, delaying one and recombine the two signals again. Measure the (fixed) time difference.
  - (2) cross-check by doubling the noise and measuring the effect on the resolution

This contibution includes also the systematics related to the method of time reconstruction by waveform analysys

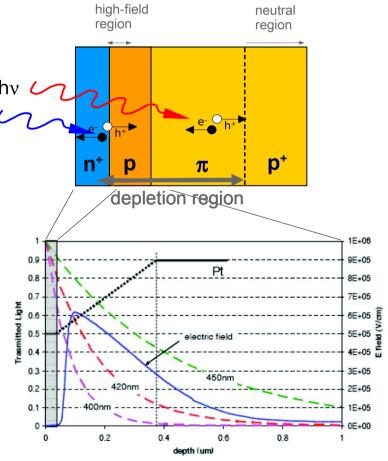
- Contribution from sampling hardware (clock jitter, ...) < 5ps</li>
- Sensitivity to the shape of the reference waveform < 5ps</li>
- Systematics from fit procedure < 5ps</li>
- Systematics from intensity dependence ~ 5ps



# IRST – single photon timing res. (SPTR)



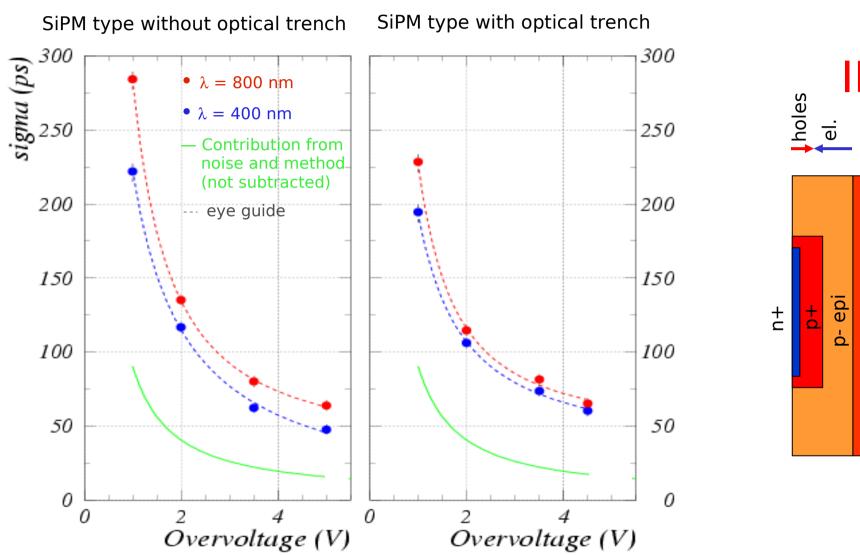
#### Better resolution for short wavelengths: carriers generated next to the peak of high E field ...



G.Collazuol et al (DASIPM collab.) NIMA 581 (2007) 461



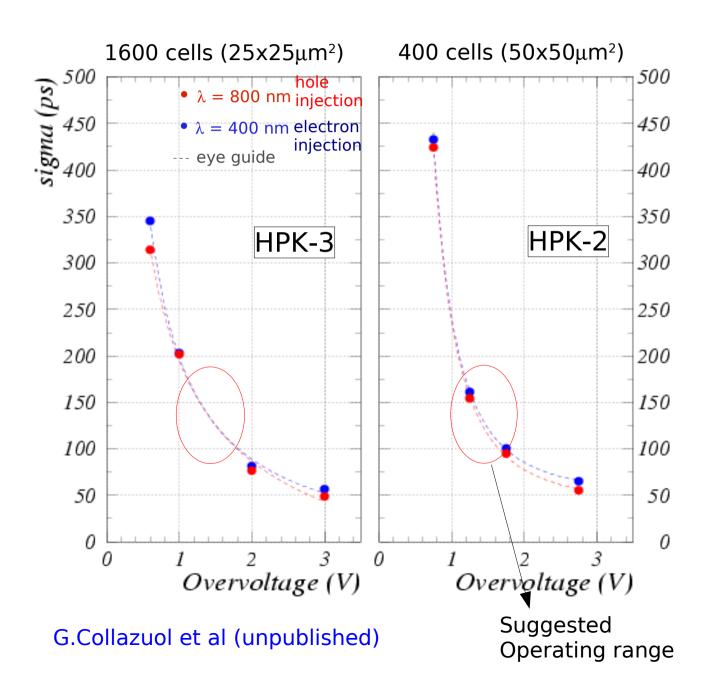
# IRST devices (different types)

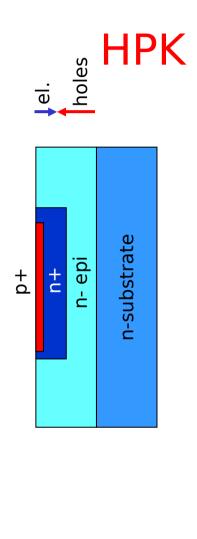


**IRST** p-substrate

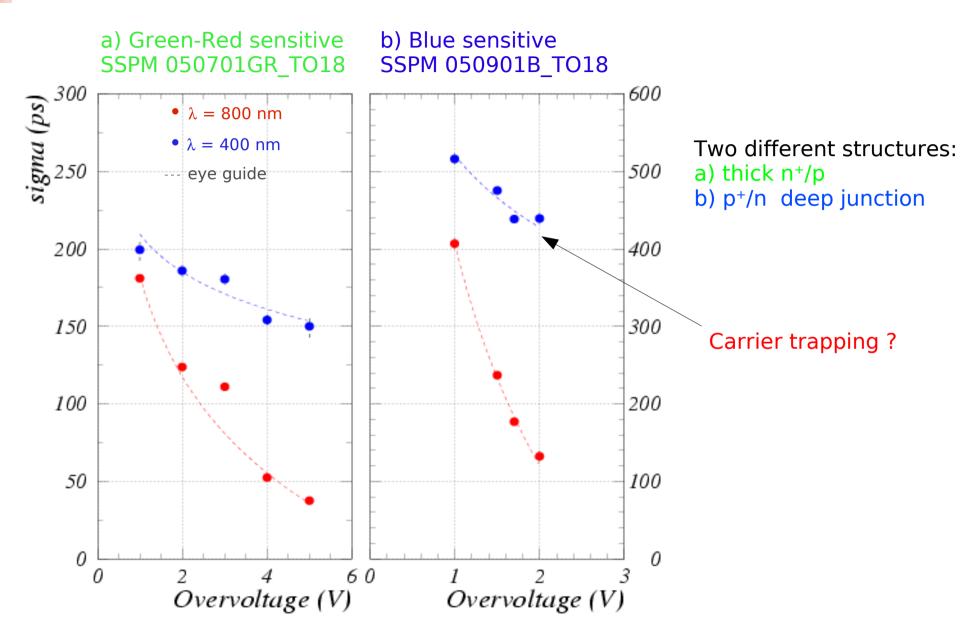
Results in fair agreement for devices with the same structure

# Hamamatsu - single photon timing res.





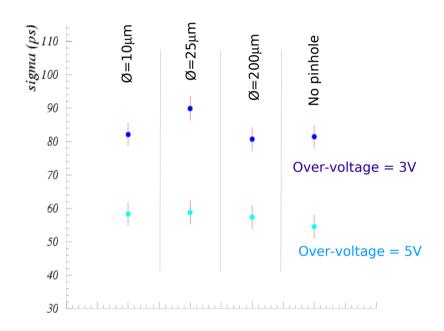
# CPTA/Photonique - single photon timing res.



G.Collazuol et al (unpublished)

# Timing studies (IRST devices)

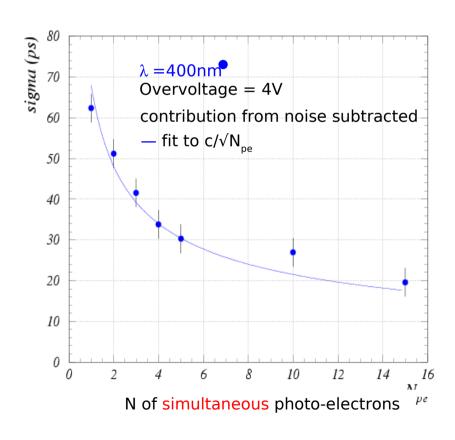
Dependence of SiPM timing on the light spot size and position (By using pinhole in front of the SiPM)



#### No relevant spread

→ Uniformity of rise-time among different cells Dependence of SiPM timing on the number of simultaneous photons

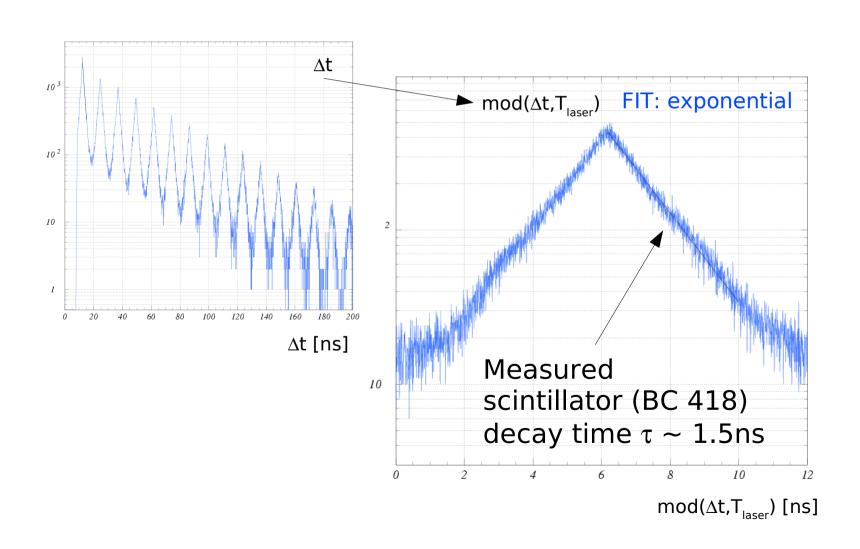
Poisson statistics:  $\sigma_t \propto 1/\sqrt{N_{pe}}$ 



# Scintillator decay time

Cross check: SiPM coupled to a fast plastic scintillator 2 x 2 x 15mm<sup>3</sup> Only the scintillator excited by the laser blue light  $\lambda$ =400nm. No direct laser light to the SiPM

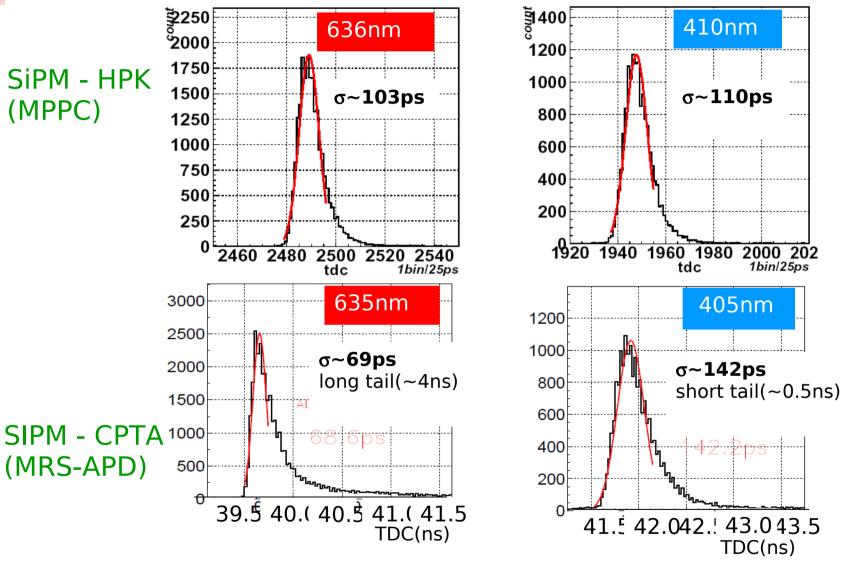
→ measurement of the scintillator decay tail



# Other studies of intrinsic Single Photon Timing Resolution (SPTR)

# SPTR: HPK/CPTA comparison

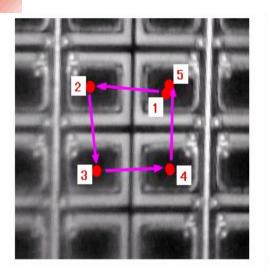
#### T.lijima – PD07 Nagoya and Lubiana groups



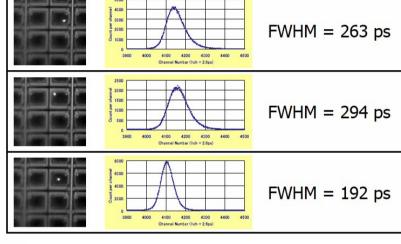
Method: CFD + TDC + Time walk corrections

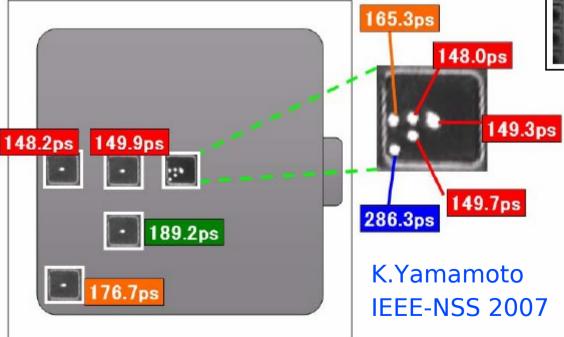
# SPTR: position dependence

Yamamoto et al (Hamamatsu)



|   | FWHM (ps) | FWTM (ps) |
|---|-----------|-----------|
| 1 | 199       | 393       |
| 2 | 197       | 389       |
| 3 | 209       | 409       |
| 4 | 201       | 393       |
| 5 | 195       | 383       |





K.Yamamoto PD07

Lower jitter if photoproduction at the center of the cell

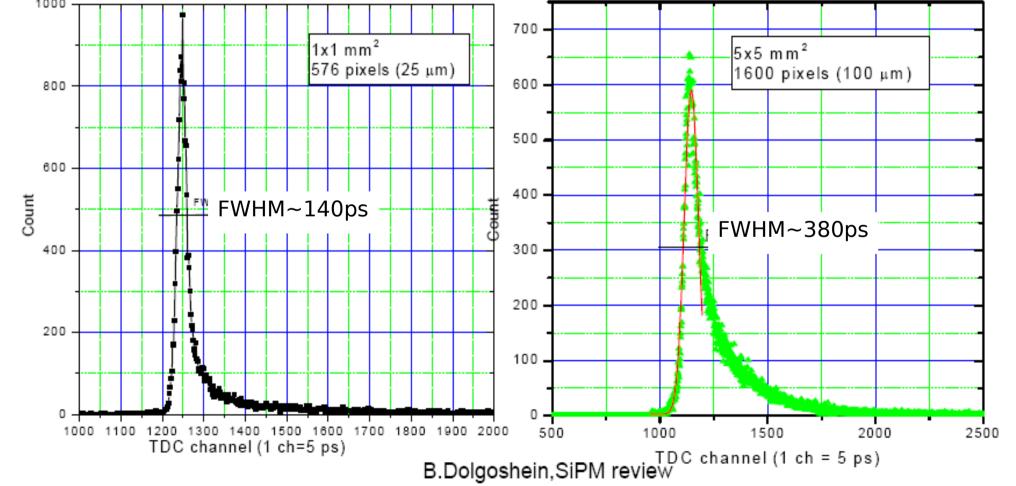
Data include the system jitter (common offset, not subtracted)

# SPTR: cell and sipm size dependence

B.Dolgoshein – LIGHT07

SiPM – MePhI/Pulsar:  $576 \text{ cells } (25x25\mu\text{m}^2)$ Area =  $1x1 \text{ mm}^2$ 

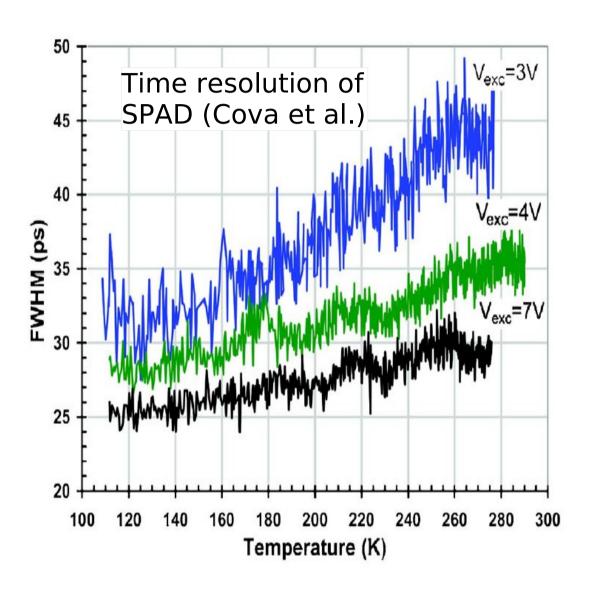
SiPM – MePhI/Pulsar:  $1600 \text{ cells } (100 \times 100 \mu \text{m}^2)$ Area =  $5 \times 5 \text{ mm}^2$ 



## SPTR: T dependence for SPAD devices

Timing: better at low T Lower jiitter at low T due to higher mobility

(Over-voltage fixed)



I.Rech el al, Rev.Sci.Instr. 78 (2007)

# Qualitative understanding of the timing and PDE characteristics...

...in view of a quantitative comparison with different models

### RPL model: fast simulation

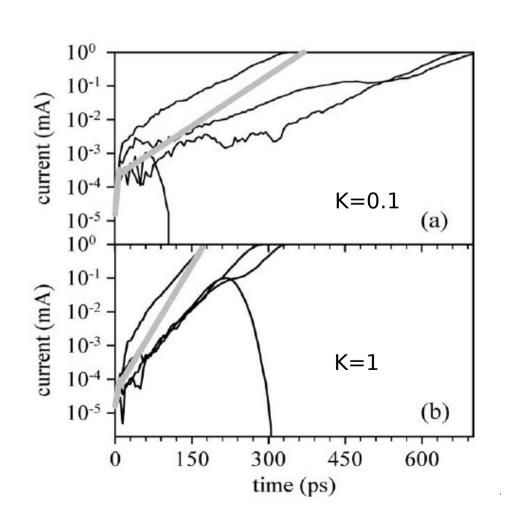
"Statistics of Avalanche Current Buildup Time in Single-Photon Avalanche diodes" C.H.Tan, J.S.Ng, G.J.Rees, J.P.R.David (Sheffield U.) IEEE J.Quantum Electronics 13 (4) (2007) 906

Numerical model (MC): Random distribution of impact ionization Path Length (RPL)

Analysis of breakdown probability, breakdown time and timing jitter as functions of avalanche region width (w), ionization coefficient ratio  $(k=\beta_{hole}/\alpha_{electron})$  and dead space parameter (d) (uniform E field, constant carrier velocity)

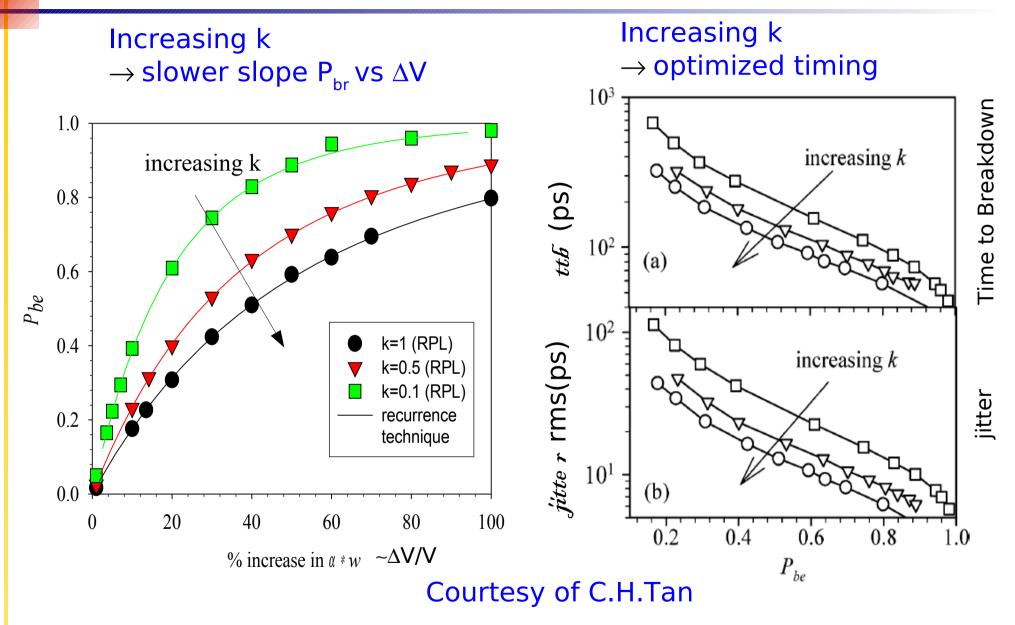
#### 1) increasing k:

- improves timing performances
- but breakdown probability
   P<sub>br</sub> increases slowly with overvoltage
- 1a) hole injection results in better timing than electron injection (in Si devices)
- 2) dead space effects worsen timing performances (the more at small k) Important for devices with small w



# RPL model

Tan, Rees, Davis et al

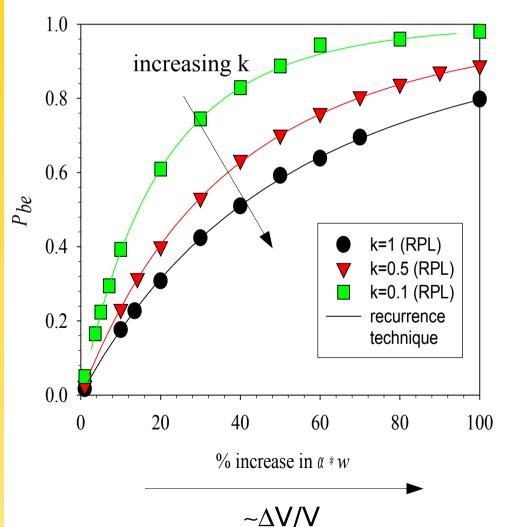


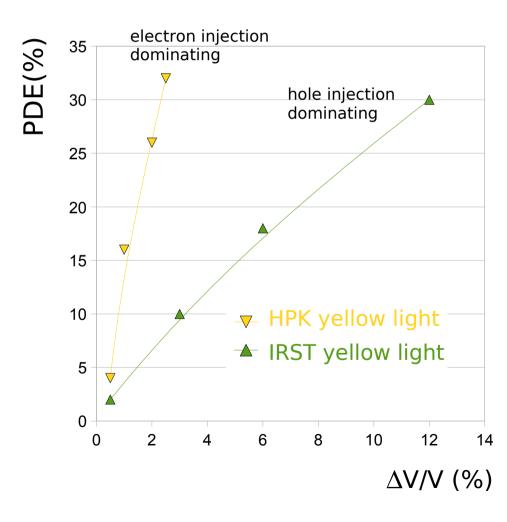
The conditions to optimize the device timing (high impact ionization ratio  $\beta/\alpha$ ) are opposite of those to optimial (fast) rise PDE vs  $\Delta V$ 

# Comparison with data ... not yet

In order to compare model with data detailed modelization will be done (ongoing work) accounting based on:

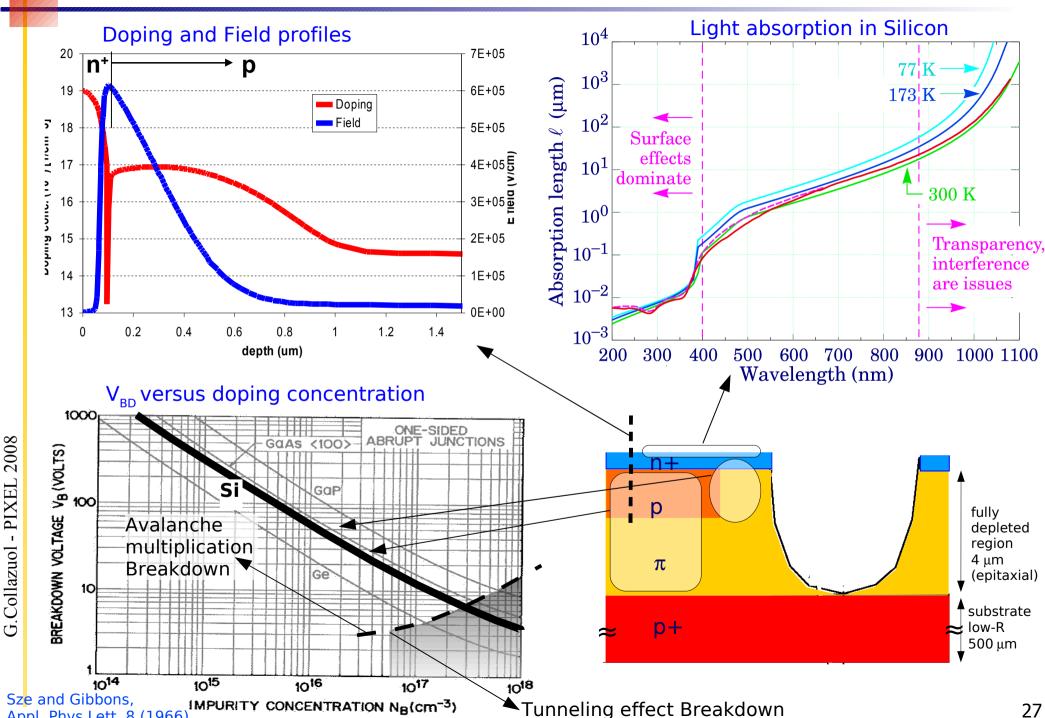
- E field profile, carrier injection profile and saturated velocities e-h
- Check with PDE and Gain





# Close up of a cell (IRST)

Appl. Phys Lett. 8 (1966)

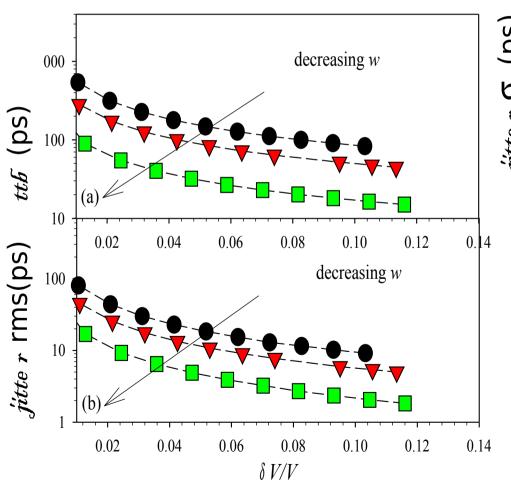


27

# Comparison with data ... not yet

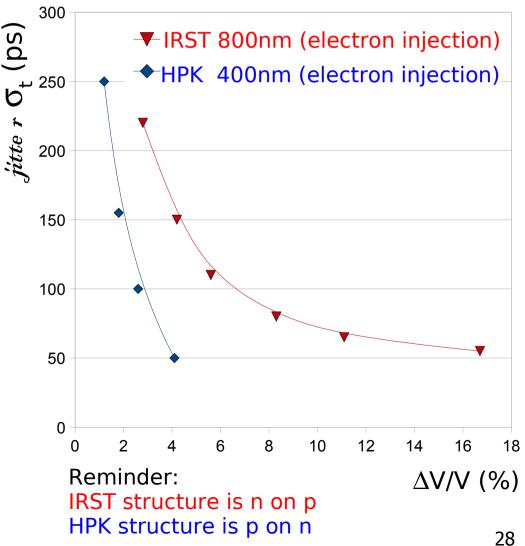
Example of RPL simulation of pure electron injection in Si SPAD

Courtesy of C.H.Tan



G.Collazuol - PIXEL 2008

DATA (DASIPM)



# Electronics for timing applications

#### Electrical model of a SiPM

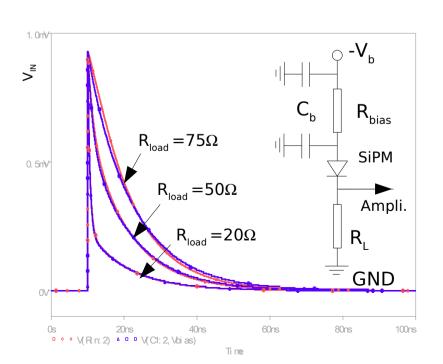
 $R_q$ : quenching resistor (hundreds of  $k\Omega$ )

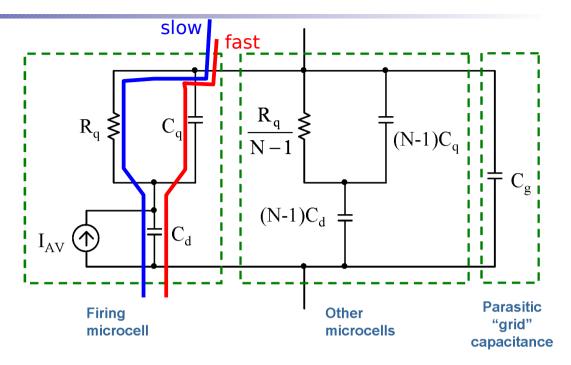
C<sub>d</sub>: junction capacitance (few tens of fF)

 $C_q$ : parasitic capacitance in parallel to  $R_q$  (few tens of fF,  $C_q < C_d$ )

 $I_{AV}$ : SiPM ~ ideal current source current source modeling the total charge delivered by a cell during the avalanche  $Q=\Delta V(C_d+C_g)$ 

C<sub>g</sub>: parasitic capacitance due to the routing of Vbias to the cells (metal grid, few tens of pF)





#### 1) the peak of $V_{IN}$ is independent of $R_s$

A constant fraction  $Q_{IN}$  of the charge Q delivered during the avalanche is instantly collected on  $C_{tot} = C_q + C_{eq}$ .

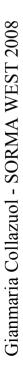
#### 2) The circuit has two time constants:

•  $\tau_{IN} = R_L C_{tot}$  (fast)

•  $\tau_r = R_q (C_d + C_q)$  (slow)

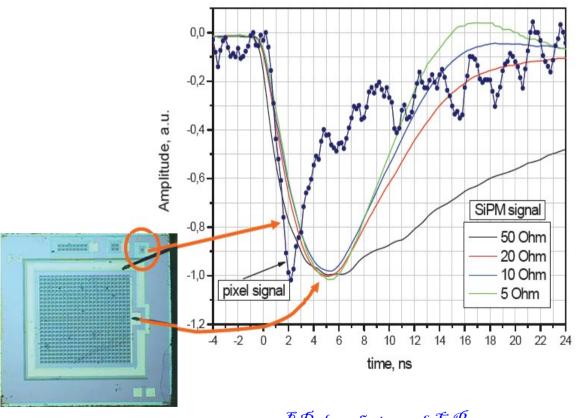
Decreasing  $R_s$ , the time constant  $\tau_{\text{IN}}$  decreases, the current on  $R_s$  increases and the collection of Q is faster

F. Corsi, C. Mazzocca et al.

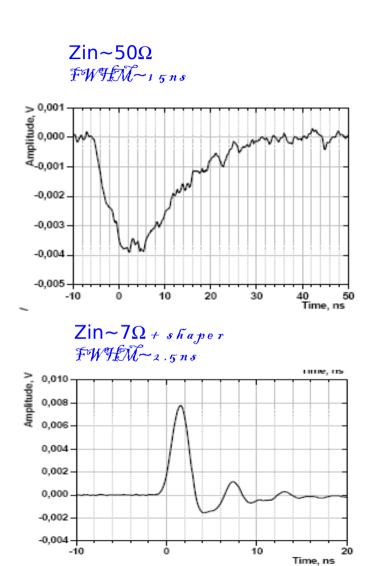


# SiPM signal: effect of C<sub>tot</sub> and Z<sub>load</sub>

SiPM - MePhI/Pulsar:  $1600 \text{ cells } (100 \times 100 \mu \text{m}^2)$ Area =  $5 \times 5 \text{ mm}^2$  $C_{tot} \sim 160 \text{pF}$ 



BDolgoshein and E.Popova LIGHT07



Trans-impedance amplifier

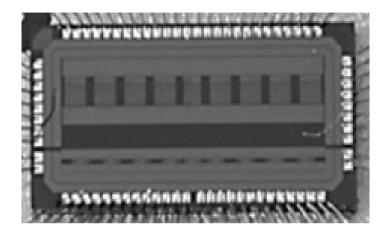
#### Ideal FE Electronics for timing (and high rate)

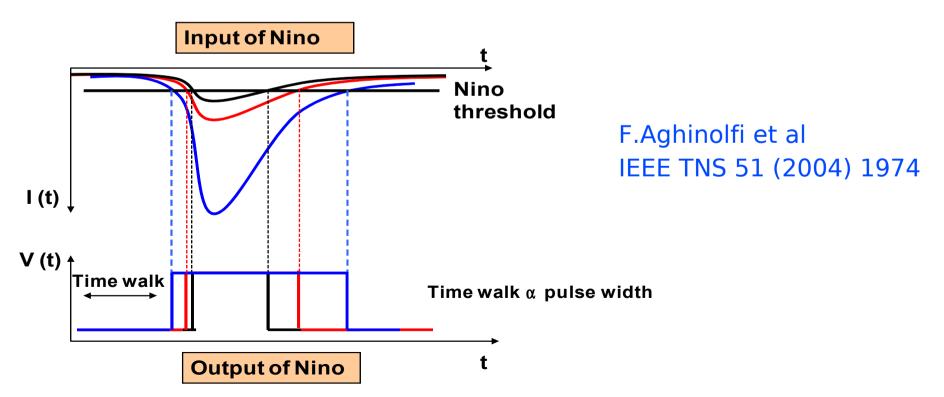
- 1) current amplifier or I-V converter:
  - exploit detector fast component  $\rightarrow$  smallest  $Z_{in}$  (and smallest  $C_{parasitic}$ )
  - detector need low external Gain  $\sim x20 \rightarrow fast amplifier$
  - detector rise time  $\sim 100 \text{ps} \rightarrow_{m \text{ a tc } h} \text{ w ith} 3 \text{GHz amplifier BW}$
- 2) RC shaper
  - → minimize signal occupancy (pile-up) per channel
  - → maximize the double pulse resolution (DPR)
- 3) sampling with FADC
  - → sampling at 1GHz time resolution better than 20 ps rms and DPR better than 5ps are easy to obtain
  - → very robust to noise
  - $\rightarrow$  cost/channel  $\sim$  O(100 \$)
- 3') Time over Threshold (ToT) Discriminator (Slew correction)
  - → time resolution better than 40 ps rms and DPR better than 10ps (depending on noise and signal shape)
  - $\rightarrow$  cost/channel  $\sim$  O(10 \$)

# Time over Threshold technique (ToT)

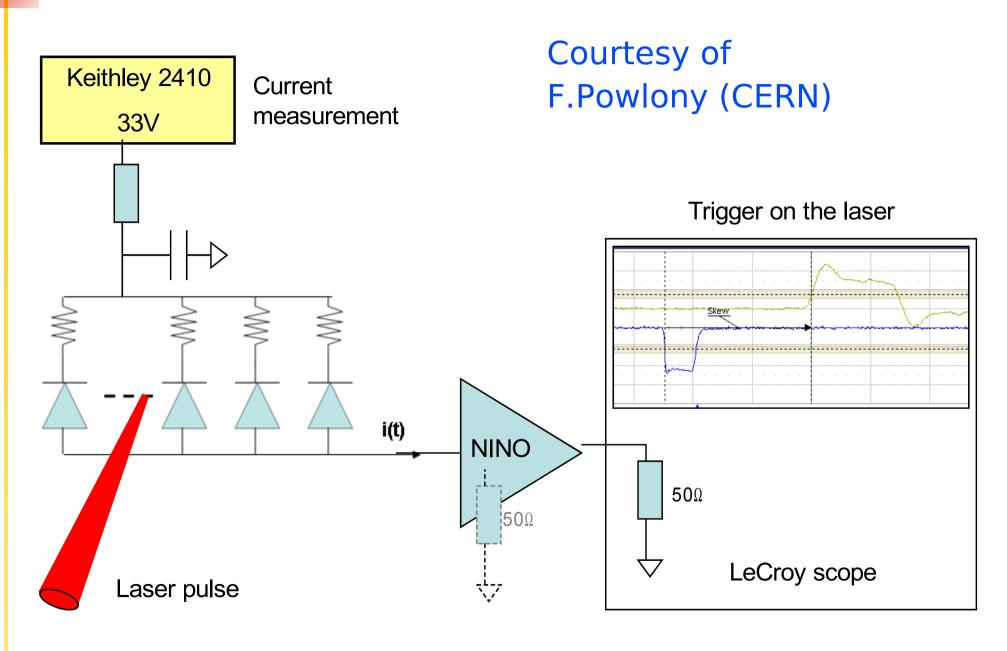
#### NHO chip

- developed for Aice TOF
- Utra-fast low-power discriminator.
- 8 channels (250 nm CMOS)
- 1 ns peaking time
- 25 ps rms time jitter
- Time over threshold technique





# Time resolution with NINO



21

21.5

22

22.5

23

23.5

24

24.5

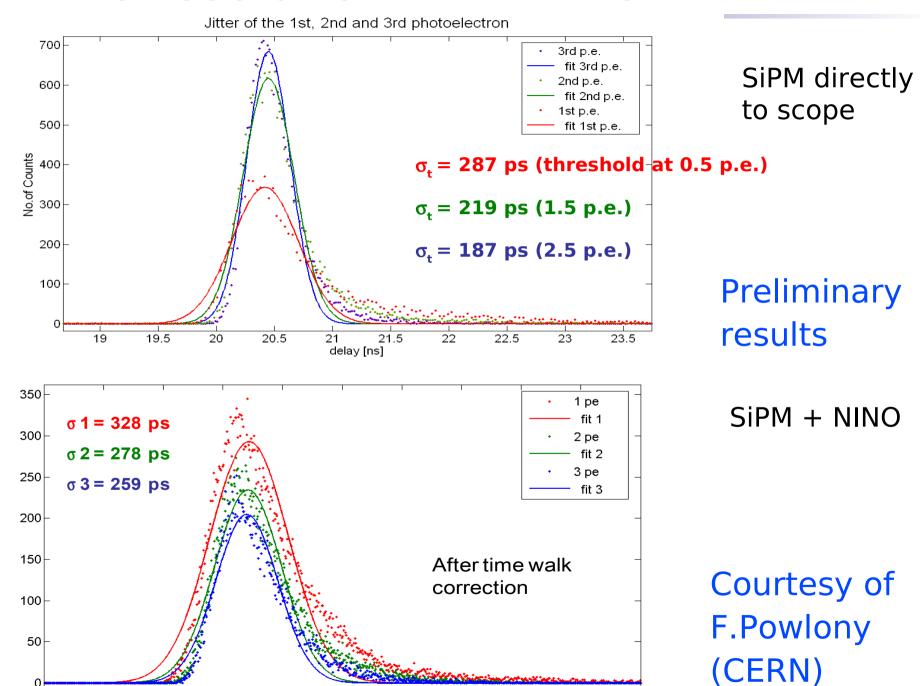
25

25.5

26



### Time resolution with NINO



# Examples of applications

# Timing with fast scintillator and SiPM

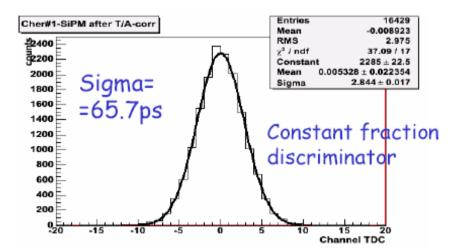
Dolgoshein Beaune05

SiPM 3x3 mm<sup>2</sup> (5600 cells) glued directly to BICRON-418 scintillator 3x3x40 mm<sup>3</sup> Signal is readout directly from SiPM without any preamp and shaper!

### Timing between:

- PMT(FEU 187) + Cherenkov radiator
- SiPM + BC418

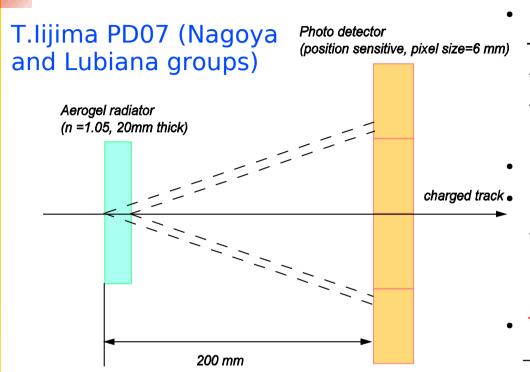




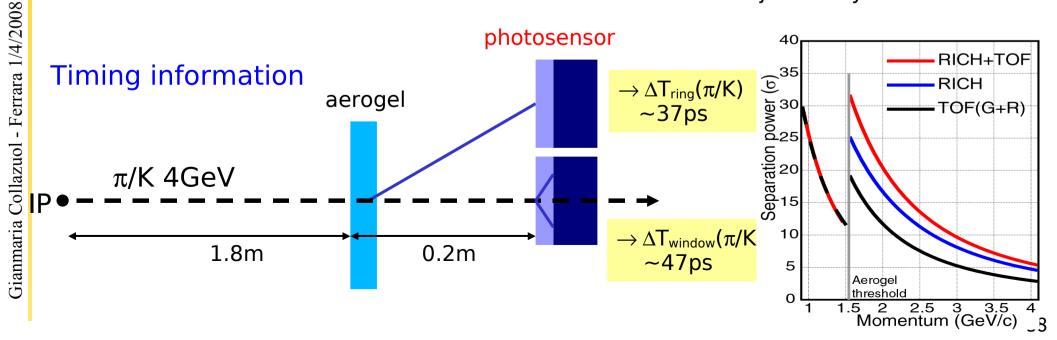
Note that the second s

$$\rightarrow \sigma_{\text{(SiPM+BC418)}} = 33.4 \text{ps}$$

# Proximity Focusing Aerogel RICH + TOF



- Proximity focusing geometry
  - aerogel radiator (n~1.05, ~2cm)
  - no mirror complex.
  - suitable for collider and space experiments
- $> 4\sigma \text{ K/}\pi \text{ for } 0.7$ 
  - Rayleigh scattering dominates in aerogel.
  - → position measurement of single photons in the visible wave length region.
- Timing measurement
  - → TOF and noise rejection by coincidences

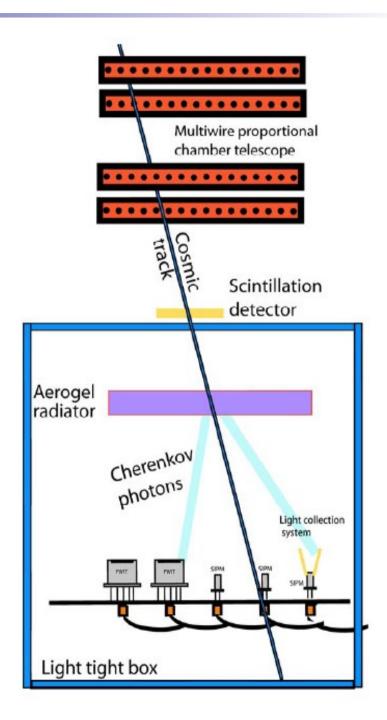


# Cherenkov tests with cosmic rays

P.Krizan (Nagoya and Lubiana groups)

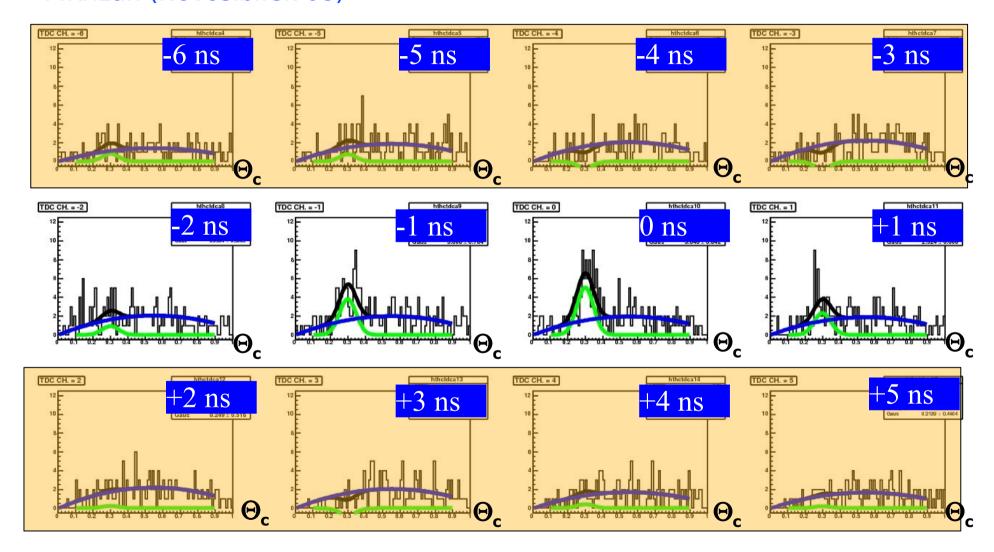
### Photon detector:

- Array of 6 SiPMs
- Array of 12 R5900-M16 PMTs as reference

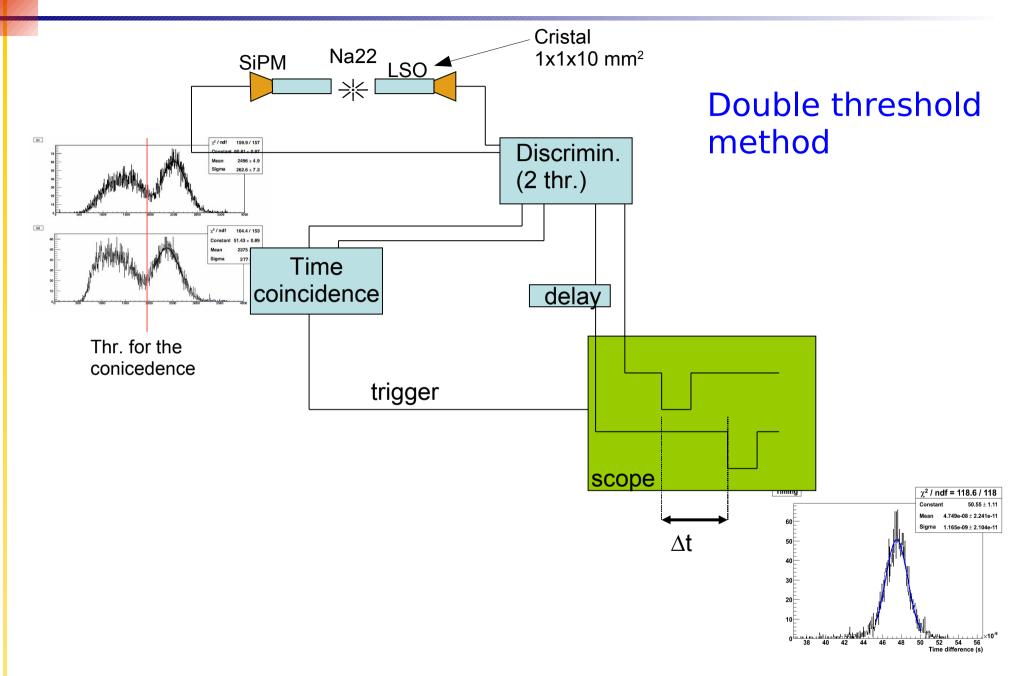


# Cherenkov tests with cosmic rays

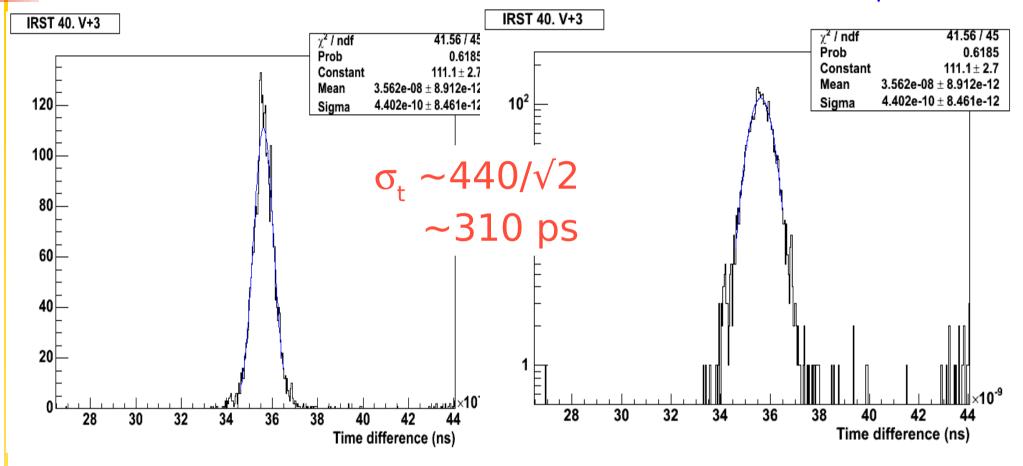
SiPM: Cherenkov angle distributions for 1ns time windows P.Krizan (Novosibirsk 08)



Cherenkov photons appear in the expected time windows >> Cherenkov photons observed with SiPMs!



SiPM - IRST -1x1 mm<sup>2</sup> (50x50μm<sup>2</sup>)

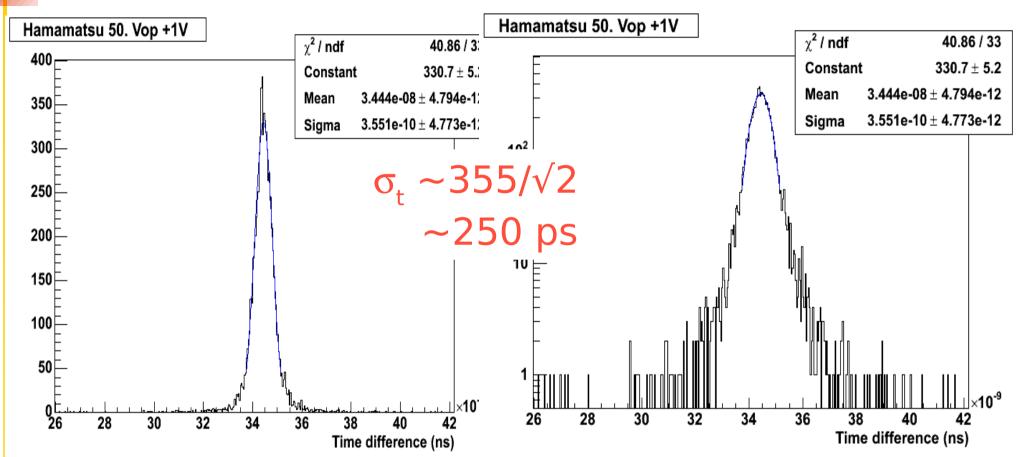


Note: 
$$\sigma_{t} \approx \frac{\sqrt{N_{\text{thr.[p.e.]}}}}{N_{\text{p.e.}}} \cdot \tau_{\text{decay}}$$
 Post P.R. 80 (1950) 1113

E.g. 
$$\tau_{decay} \sim 40 \text{ns} \text{ (decay time for LSO)}$$
  $N_{p.e.} \sim 100 \text{ p.e. (photopeak)}$   $N_{thr.} \sim 1 \text{ p.e. (trigger on 1}^{st} \text{ p.e.)}$ 

Expected:  $\sigma_{t} \sim 400 \text{ ps}$ 

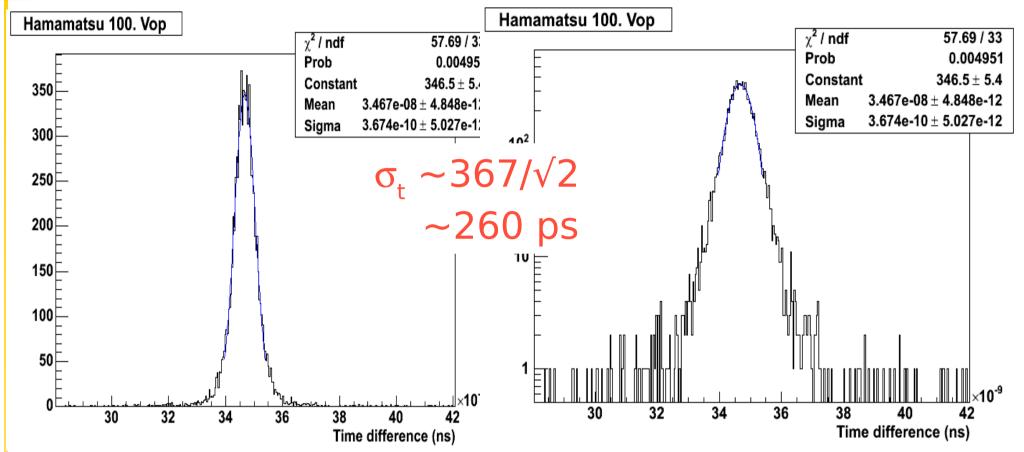
SiPM – HPK 1x1 mm<sup>2</sup> (50x50μm<sup>2</sup>)



More photoelectrons (higher PDE)

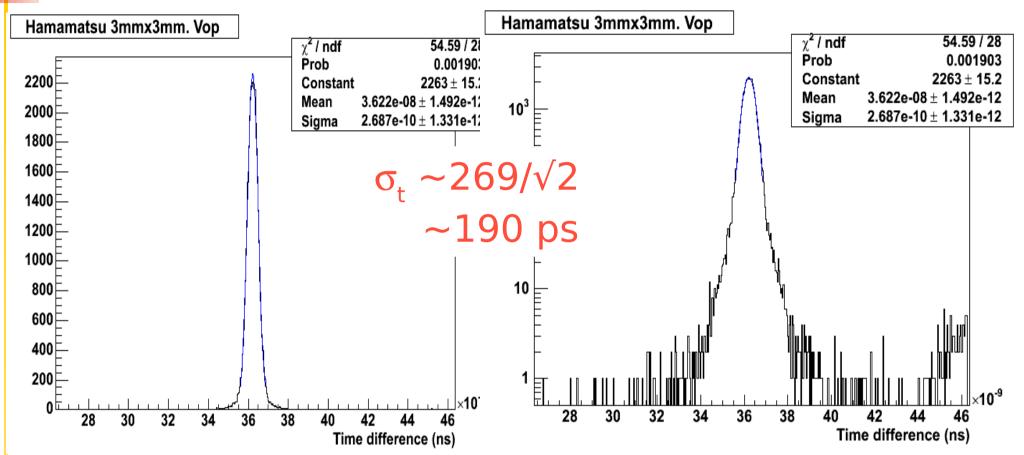
G.Llosa, DASIPM (unpublished)

SiPM - HPK -1x1 mm<sup>2</sup> (100x100μm<sup>2</sup>)



G.Llosa, DASIPM (unpublished)

SiPM – HPK .3x3 mm<sup>2</sup> (50x50μm<sup>2</sup>)



G.Llosa, DASIPM (unpublished)

# Conclusions

SiPM are intrinsically very fast:

- core (gaussian) fluctuations below 100ps, depending on ΔV
- Non gaussian tails up to O(ns), depending on wavelength

The conditions to optimize the device timing (high impact ionization ratio  $\beta/\alpha$ ) are opposite of those to optimial (fast) rise PDE vs  $\Delta V$ 

High bandwidth current amplifier + fast sampling electronics best choice for timing applications (robust against noise and pile-up)

Best (gaussian) resolutions in applications:

- Cherenkov: O(10ps)
- Fast plastic scintillators O(20ps)
- Fast crystal scintillators O(150ps)

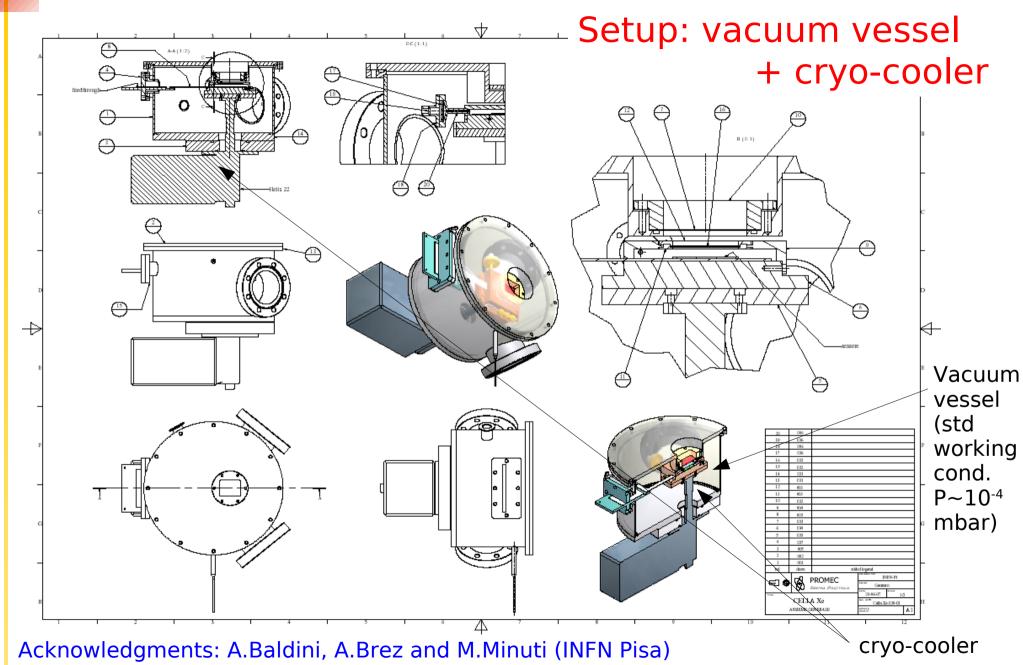
Non-gaussian tails to be considered (for long wavelengths)

# Appendix:

Recent measurements about temperature dependence of SiPM parameters

# G.Collazuol - PIXEL 2008

# Temperature characterization



# T dependence: $V_{\text{BD}}$ , $\tau_{\text{Q}}$ and Gain

# V<sub>BD</sub> breakdown voltage: V<sub>BD</sub> increases with T:

At higher T carriers loose more to lattice

- $\rightarrow$  lower mobility, shorter mean free path ( $\lambda$ )
- $\rightarrow$  carriers need higher V to impact-ionize (temp. coefficient  $\Delta V_{BD}/\Delta T \sim 20 \text{mV/K} 80 \text{mV/K}$  depending on doping concentration)

Recovery time:  $\tau_0$  decreases with T

Due polysilicon  $R_{Q}$  properties

| T (K) | $Rq(M\Omega)$ |
|-------|---------------|
| 300   | 0,2           |
| 200   | 0,4           |
| 77    | 1,7           |

H.Otono - PD07 Characterization of SiPM by HKP at low T

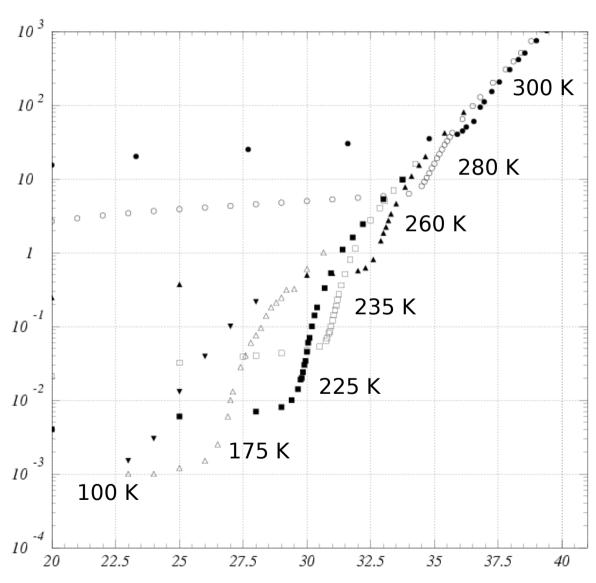
Cell Capacity does not vary with T

Gain independent of T at fixed Over-Voltage



# I-V measurements at different T

SiPM - IRST (1x1mm<sup>2</sup>, fill factor 50%)

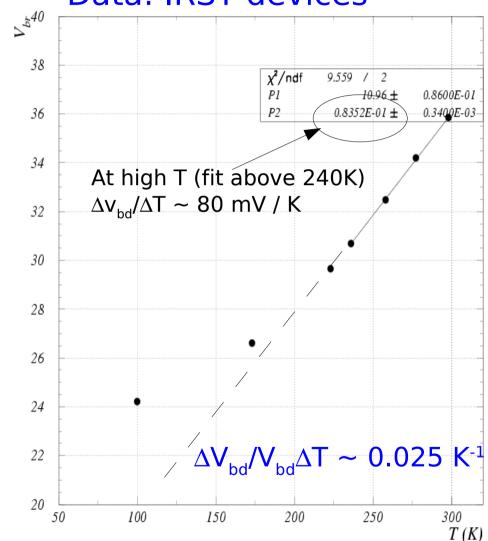




G Callamal - DIXEL 2008

# V<sub>BD</sub> Break-Down vs T





G.Collazuol (unpublished)

### Model: Baraff PR 128 (1962) 2507

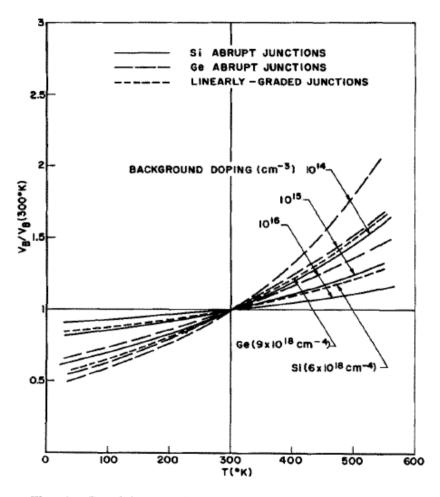
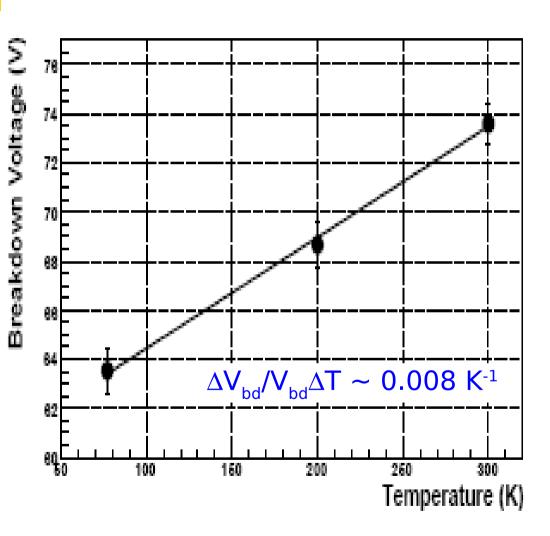


Fig. 4. Breakdown voltage vs temperature for Si and Ge p-n junctions.  $V_B(300^{\circ}\text{K})$  is 2000, 330, and 60 V for Si and 950, 150, and 25 V for Ge for dopings of  $10^{14}$ ,  $10^{15}$ , and  $10^{16}$  cm<sup>-3</sup> respectively. The linear-graded junctions have  $V_B(300^{\circ}\text{K})$  the same as those for doping of  $10^{15}$  cm<sup>-3</sup>.

Crowell and Sze, APL 9 (1966) 242

# V<sub>BD</sub> Break-Down vs T

### Data: HPK devices



Otono et al - PD07

### Model: Baraff PR 128 (1962) 2507

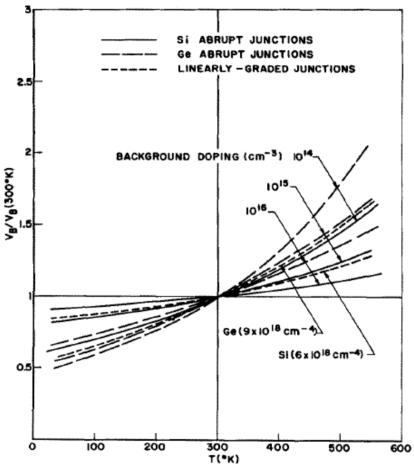


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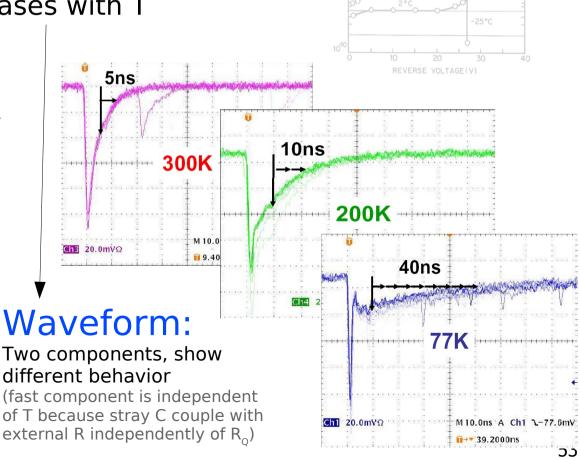
Due polysilicon  $R_Q$  properties

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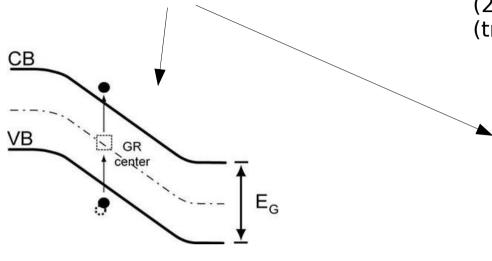
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Gain independent of T at fixed Over-Voltage

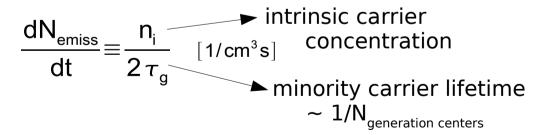


# Dark count rate: free carrier generation

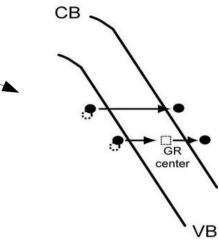
### Two main mechanisms



(1) Generation - Recombination Centers SHR generation (Field Enhanced) in the depletion region



(2) Field-Assisted Generation: tunneling (trap-assisted and band to band)



### Example:

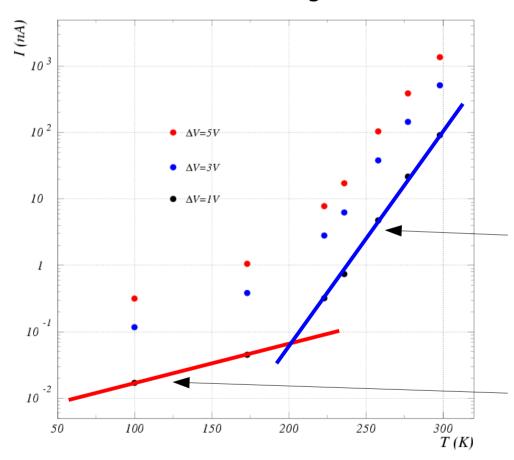
- effective volume  $V_{eff} = A_{eff} \cdot W_{depletion}$  $V_{eff} \sim 1 \text{mm}^2 \cdot 50\% \cdot 4 \mu \text{m}$
- $\tau_a \sim 10$ ms (good quality technology)
- Prob. to trigger avalanche P<sub>01</sub>  $P_{01}^{e} \sim 100\%$  for electrons  $P_{01}^{h} \sim 1/2 P_{01}^{e} \sim 50\%$  for holes

 $\rightarrow$  Dark rate  $\sim V_{eff} P_{01} / \tau_g \sim 2 MHz$  (n+/p: e trigger the avalanche in depl. region)  $\sim$  1MHz (p+/n: h trigger the avalanche in depl. region)  $_{54}$ 

# T dependence: Dark Current

### Data (IRST devices)

(fixed over-voltage)



### Dark rate sources:

### 1. Diffusion

I<sub>reverse</sub> by minority carriers: negligible ay T room

### 2. SHR (Field Enhanced)

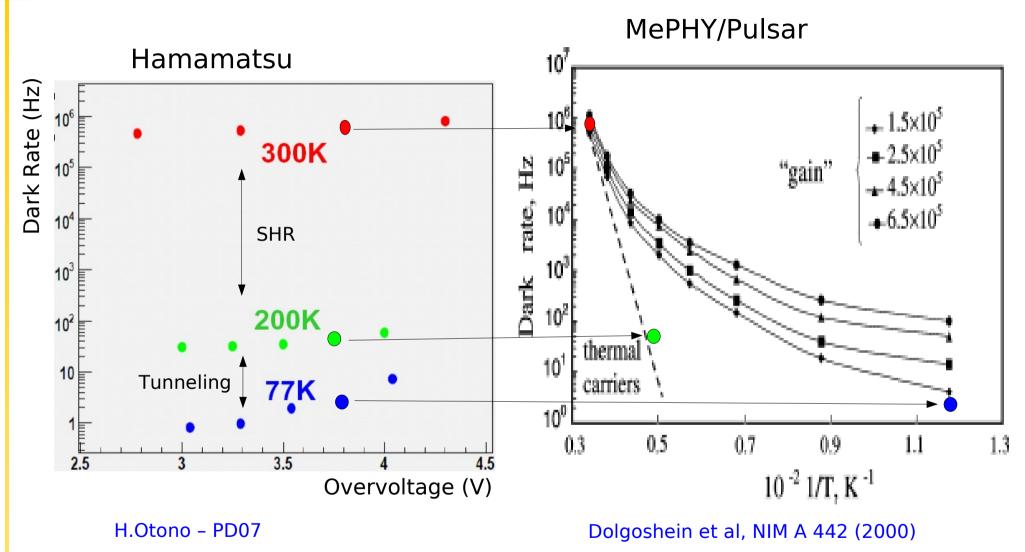
Rule of thumb: factor x2/8k (at fixed Over-voltage) Dominates at T room  $I_{reverse} \propto T^2 exp \frac{-E_g}{2 \, K_s \, T}$ 

### 3. Band to band Tunnel

Strong dependence on the Electric field profile May dominate at low T

G.Collazuol (unpublished)

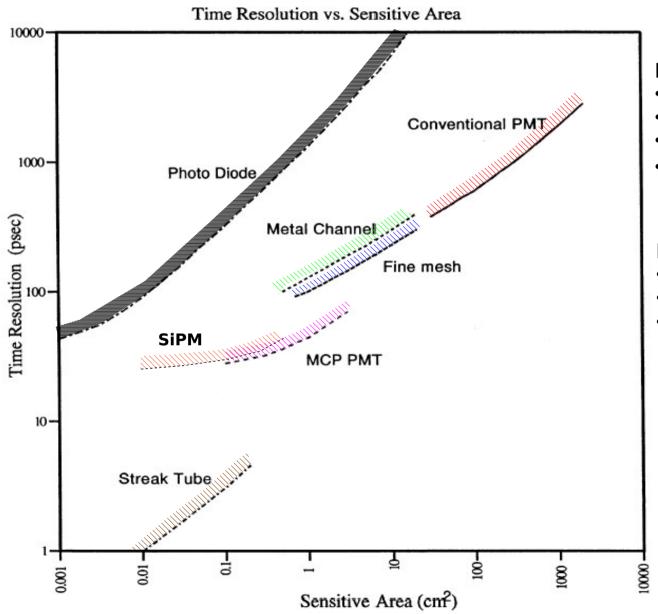
# T dependence: Dark Rate



Electric field engineering and silicon quality make huge differences in dark noise as a function of T

# **Spares**

# Timing resolution of photo-detectors



### Note resolution improves:

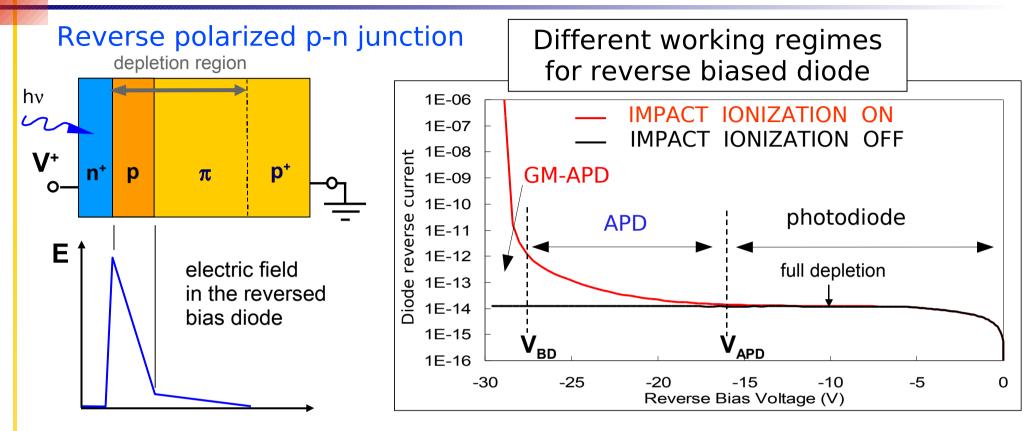
- by decreasing active area
- by decreasing the intrinsic
- detector capacitance
- as  $\sigma_t/t \sim 1/\sqrt{Npe} \sim 1/\sqrt{QE}$

### Note tails matter:

- MCP
- APD < 2ns at 1/10<sup>5</sup> (best)
- SiPM < 1ns at  $1/10^2$  (only large $\lambda$ )

modified from K.Arisaka NIMA 422 (2000)

# The building block of a SiPM: GM-APD



### APD: Linear-Proportional Mode

- Bias BELOW  $V_{BD}$  ( $V_{APD} < V < V_{BD}$ )
- It's an AMPLIFIER
- Gain: limited < 1000 due to fluctuations
- $\bullet$  Strong dependence on T and  $V_{\mbox{\tiny bias}}$
- No single photo-electron resolution

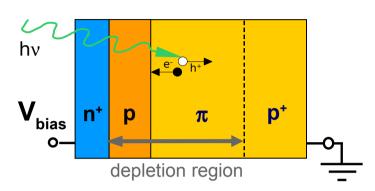
### GM-APD: Geiger Mode

- Bias ABOVE  $V_{BD}$  (V- $V_{BD}$  ~a few volts)
- It's a TRIGGER (BINARY) device
- Gain:  $\rightarrow \infty$
- Limited by dark count rate
- Single photo-electron resoution

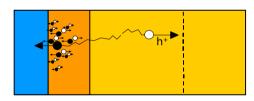
# Operation principle of a GM-APD

### Diode Biased ABOVE V<sub>BD</sub>

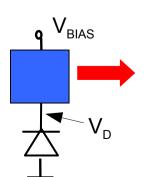
• t=0: carrier initiate the avalanche



• 0<t<t₁: avalanche spreading



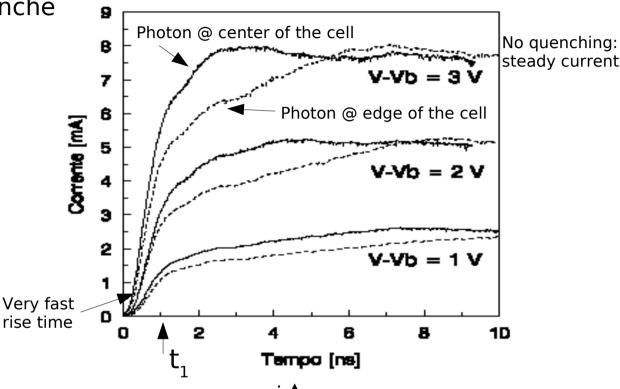
 t<sub>1</sub><t: self-sustaining current (limited by series resistances )

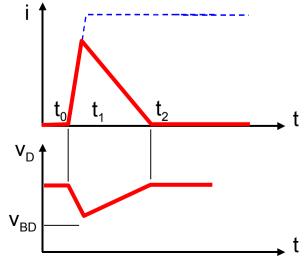


To detect another photon need a quenching mechanism. Two solutions:

- large resistance: passive quenching
- analog circuit: active quenching

A.Spinelli Ph.D thesis (1996)



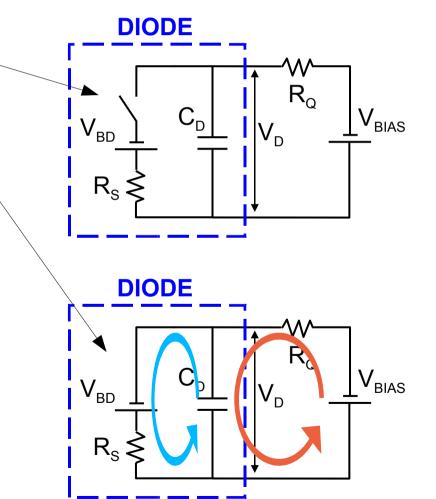


### Electrical model of a GM-APD

Passive quenching studied in detail in the '60 to model micro-plasma instabilities McIntrye JAP 32 (1961), Haitz JAP 35 (1964)

The Geiger-Mode APD can be modeled with an electrical circuit and two probabilities:

- Switch OFF = micro-plasma non-conducting
- Switch ON = micro-plasma conducting
- C<sub>d</sub> diode capacitance (some 10fF)
- $R_s$  series resistance ( $\sim 1k\Omega$ )
- $R_{\alpha}$  quenching resistance (> 300k $\Omega$ )
- $V_{bd}$  <  $V_{bias}$  (few % relative)
- P<sub>01</sub> turn-ON
   Probability that a carrier traversing the high field region trigger an avalanche
- P<sub>10</sub> turn-OFF
   Probability that number of carriers in the high field region fluctuates to 0



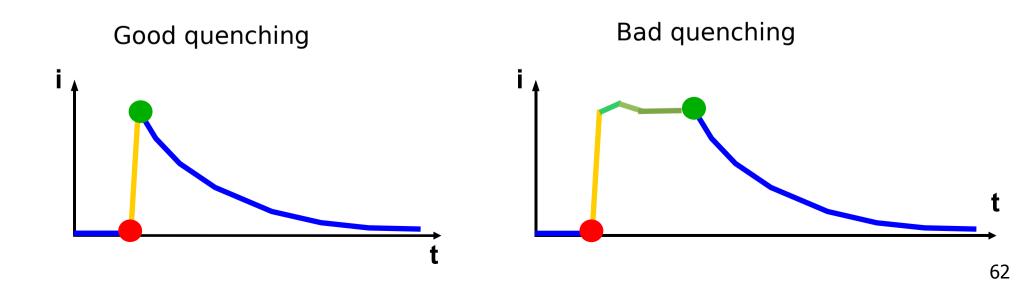
# Operation principle of a GM-APD

In GM-APD the detection of a photon essentially triggers the full discharge of a condenser!

Gain = charge on the condenser / electron charge.

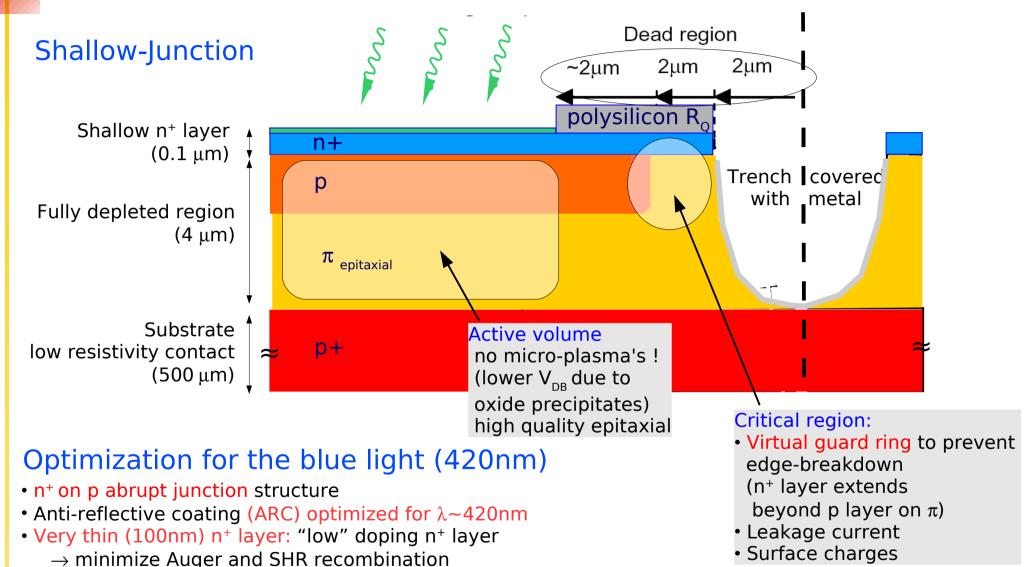
The Gain fluctuations in GM-APD are very small and different in nature compared to APD where the statistical process of internal amplification shows peculiar fluctuations (multiplication noise)

Note: effective quenching (R<sub>o</sub>) is crucial to have a well defined gain



# Close up of a cell (IRST technology)

• Thin high-field region: "high" doping p layer (limited by tunneling breakdown)



- ightarrow fixes  $V_{BD}$  junction well below  $V_{BD}$  at edge  $\bullet$   $R_{O}$  by doped polysilicon
- Trenches for optical insulation (low cross-talk)
- Fill factor: 20% 80%

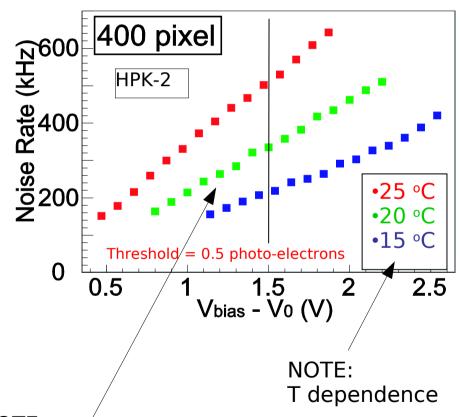
# Dark count rate

Critical issues: • quality of epitaxial layer

gettering techniques

### Hamamatsu device (1mm²)

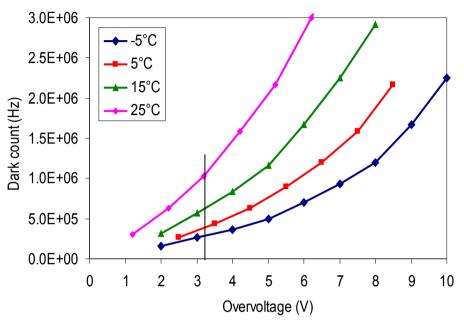
S.Uozumi - Vienna VCI 2007



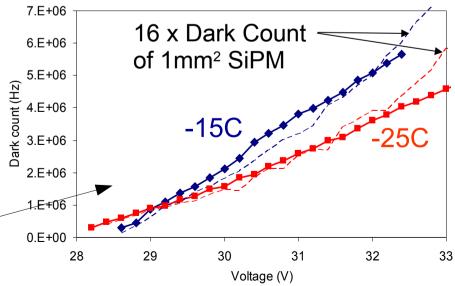
### NOTE:

- ~ linear dependence due to  $P_{01} \propto \Delta V$
- ~ scales with active surface
- ~ non-linear at high  $\Delta V$  due to additional rate from cross-talk ( $\propto \Delta V^2$ )

### IRST device (1x1 mm<sup>2</sup>)



### IRST device (4x4 mm<sup>2</sup>)



# Detector performances

related to the recharge of the diode capacitance from  $V_{\rm BD}$  to  $V_{\rm bias}$  during the avalanche quenching time after  $I_{\rm latch}$  is reached.

 $G=(V_{BIAS}-V_{BD})*C_{D}/q$  valid for few volts above  $V_{BD}$ 

Noise: dark count afterpulse optical cross-talk

### PDE = QE \* $P_{01}$ \* $\epsilon$

QE = quantum efficiency

 $P_{01}$  = avalanche triggering prob.

 $\epsilon$  = geometrical fill factor

### Dynamic Range

Related to the photogeneration and to the avalanche propagation

Gain

pulses triggered by non-photogenerated carriers (thermal / tunneling generation in the bulk or in the surface depleted region around the junction)

carriers can be trapped during an avalanche and then released triggering another avalanche

photoegeneration during the avalanche discharge. Some of the photons can be absorbed in the adjacent cell possibly triggering new discharges

### Photo-detection efficiency

Related to the density of cells and recovery time

Time resolution

# .Collazuol - PIXEL 2008

# Photo-detection efficiency (PDE)

PDE = 
$$N_{pulses} / N_{photons} = QE \cdot P_{01} \cdot \epsilon_{geom}$$

# Carrier Photo-generation

(QE = probability for a photon to generate a carrier that reaches the high field region)



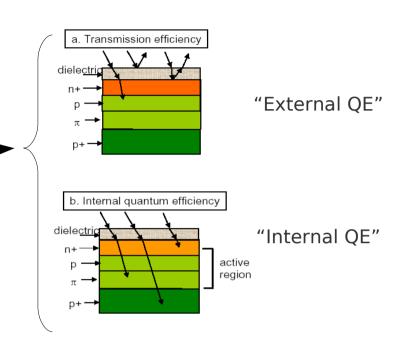
# Avalanche triggering

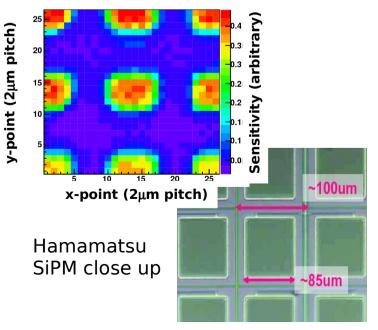
 $(P_{01} = probability for a carrier traversing the high-field to generate the avalanche)$ 



### Geometrical fill factor

 $(\epsilon = \text{fraction of dead area due to structures between}$  the cells, eg. guard rings, trenches)





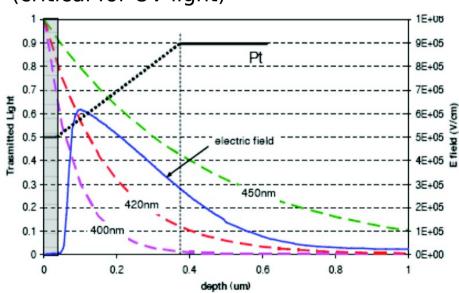
# QE: Efficiency of a single cell

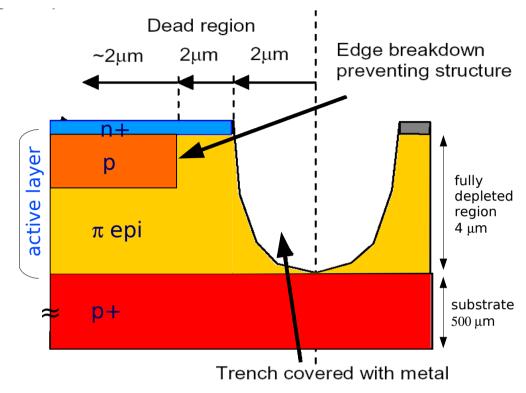
### Two factors in QE:

- (1) transmittance of the entrance window (dielctric on top of silicon surface)
- (2) probability of a photon inside to generate a e-h pair in the active layer (internal quantum efficiency)

Only the depleted region is fully active to efficiently photo-generate because of high recombination probability in the un-depleted regions.

Only a small layer  $(\lambda_{diffsion} \sim \sqrt{D\tau_{recomb}})$  at the edge of un-depleted regions contributes to the photo-generation (critical for UV light)



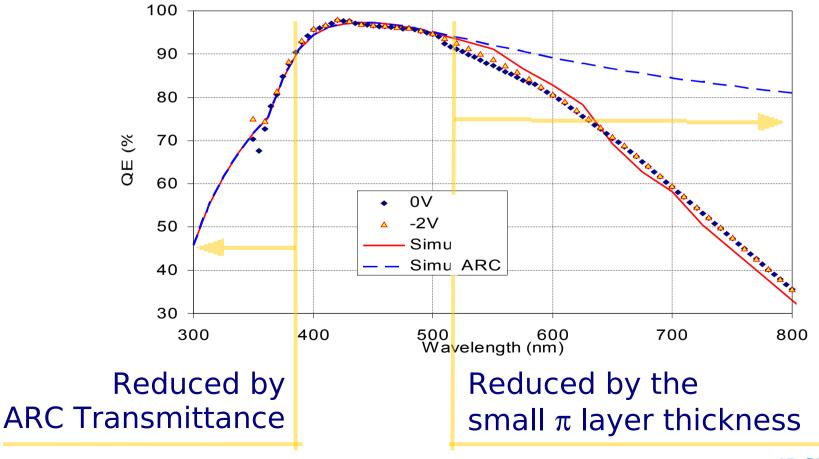


### **QE** optimization

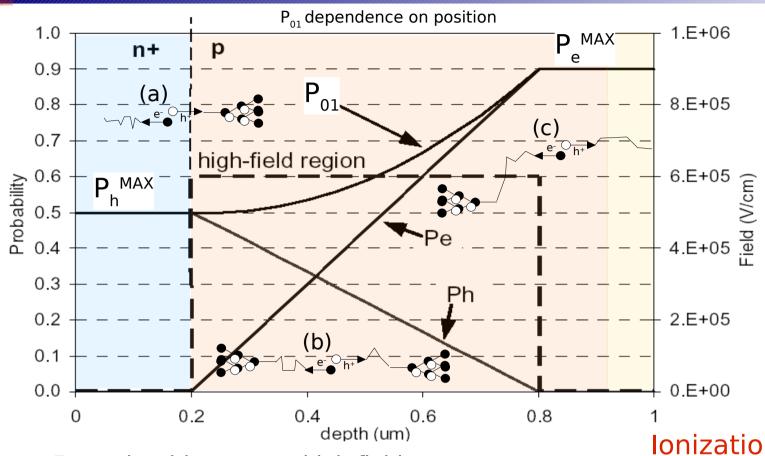
- Anti-reflective coating (ARC)
- Shallow junctions for short  $\lambda$
- Thick epi layers for long  $\lambda$

# QE: Efficiency of a single cell

Direct access to internal QE and transmittance through ARC by measuring photo-voltaic regime ( $V_{bias} \sim 0 \text{ V}$ ) the photon detection efficiency of a diode with the same n<sup>+</sup>/p junction structure and same ARC



# Avalanche trigger probability (P<sub>01</sub>)



C.Piemonte NIM A 568 (2006) 224

### Example with constant high-field:

- (a) only holes may trigger the avalanche
- (b) both electrons and holes may trigger (but in afraction of the high-field region)
- (c) only electrons may trigger

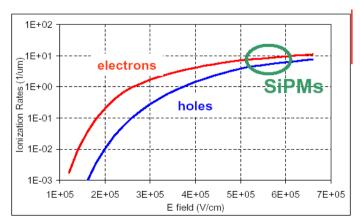
### high over-voltage

## P<sub>01</sub> optimization



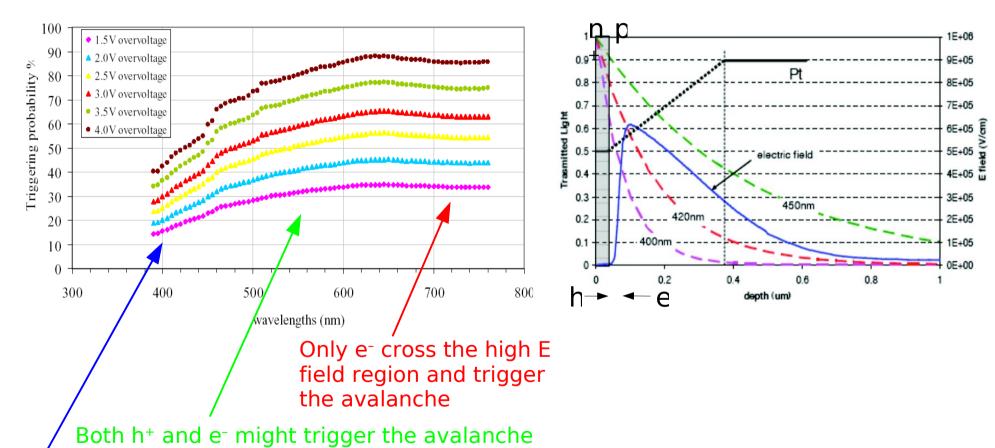
photo-generation in the p-side of the junction

### Ionization rate in Silicon



# Avalanche trigger probability (P<sub>01</sub>)

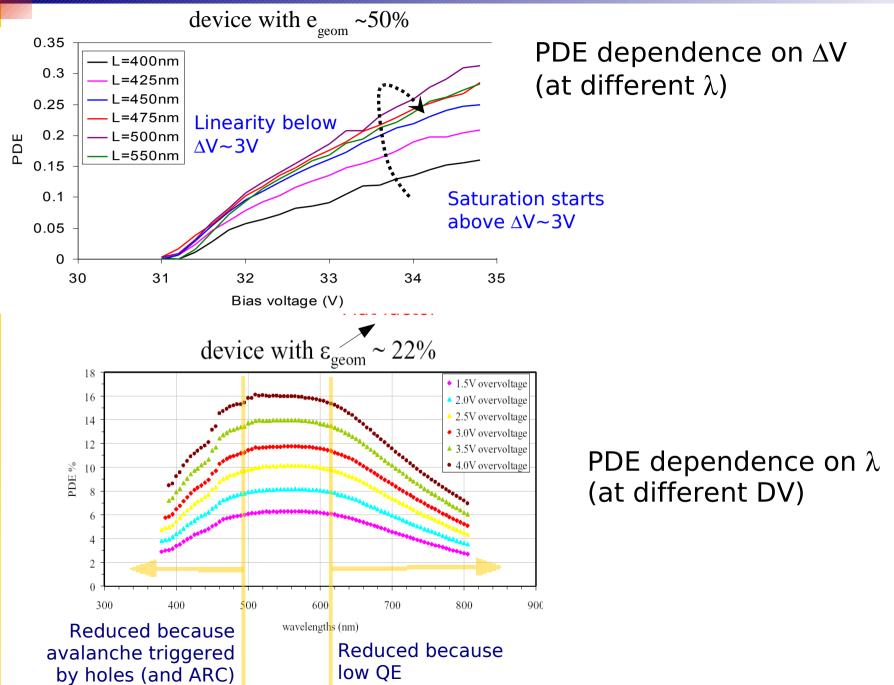
$$P_{01}$$
= PDE / QE /  $\epsilon_{geom.}$ 



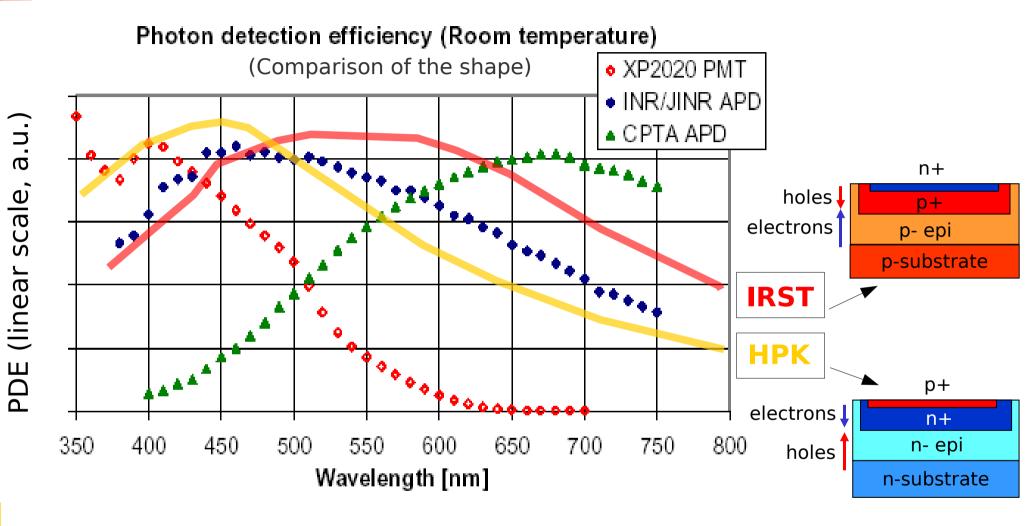
Only h+ cross the high E field trigger the avalanche

(but cross only a fraction of high field region)

# IRST devices – PDE vs over-voltage and $\lambda$



# PDE VS wavelength shape: comparison



### NOTE:

- The absolute scale (peak value) is set by fill factor (up to 70%) and over-voltage
- Obviously PDE shape is extremely dependent of the structure:
   p-on-n (where essentially electrons trigger avalanches for short wavelengths) is naturally more blue sensitive than n-on-p (holes trigger avalanches for short wavelengths)
- The use of WLS on the surface (enhance PDE to short wl) degrades the timing resolution

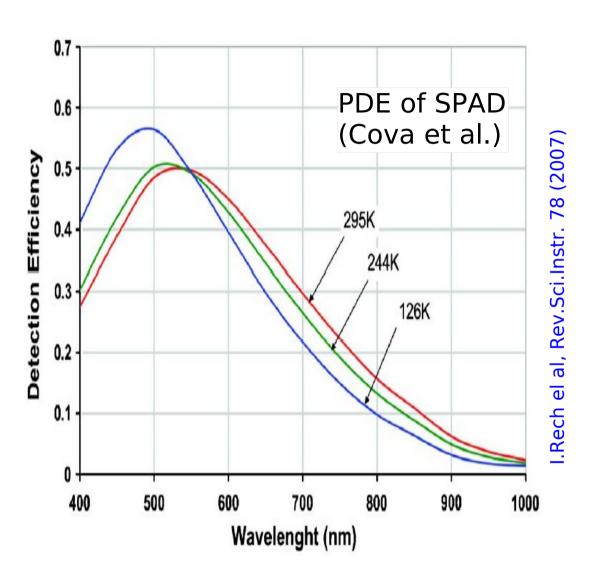
# T dependence: PDE (SPAD devices)

# PDE dependence on T (Over-voltage fixed)

Combination of two effects:

- P<sub>01</sub> increases at low T because of increased impact ioniz.
- Energy gap increases at low T

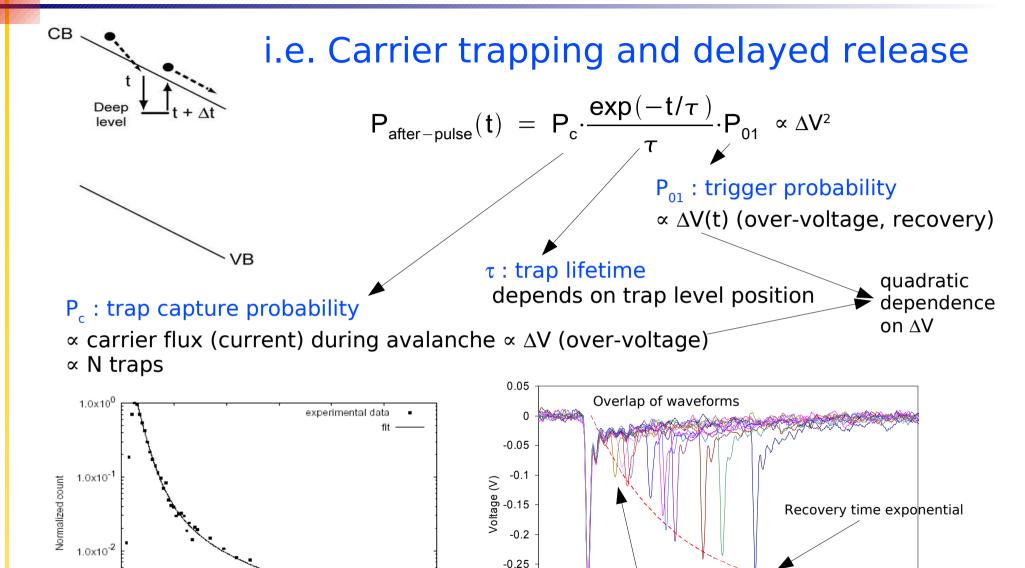
Similar effect expected also for SiPM



1.0x10<sup>-3</sup>

# After-pulsing (delayed noise)

2.5e-07



-0.3

-0.35

-1.0E-08

Fig. 10. Spectrum of the delay time from the primary pulse to the after-pulse. C.Piemonte et al. IEEE TNS 54 (1) (2007) 236

Delay (s)

5e-08

It can be reduced to % in a wide  $\Delta V$  range

3.0E-08

Time (s)

5.0E-08

7.0E-08

more probable at short delays

After-pulsing

1.0E-08

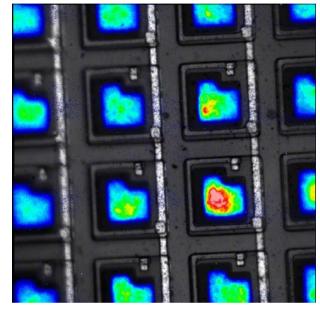
# Optical cross-talk (excess noise)

Carrier luminescence (spontaneous direct relaxation in the conduction band) during the avalanche: probability 3•10<sup>-5</sup> per carrier (crossing the junction) to emit photons with E> 1.14 eV

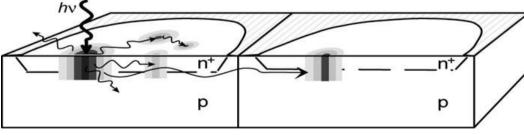
A.Lacaita et al. IEEE TED (1993)

Photons can induce avalanches in neighboring cells. Depends on distance between high-field regions Quadratic dependence on over-voltage:

- carrier flux (current) during avalanche  $\propto \Delta V$
- gain ∝ ∆V

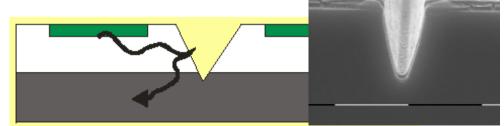


N.Otte, SNIC 2006

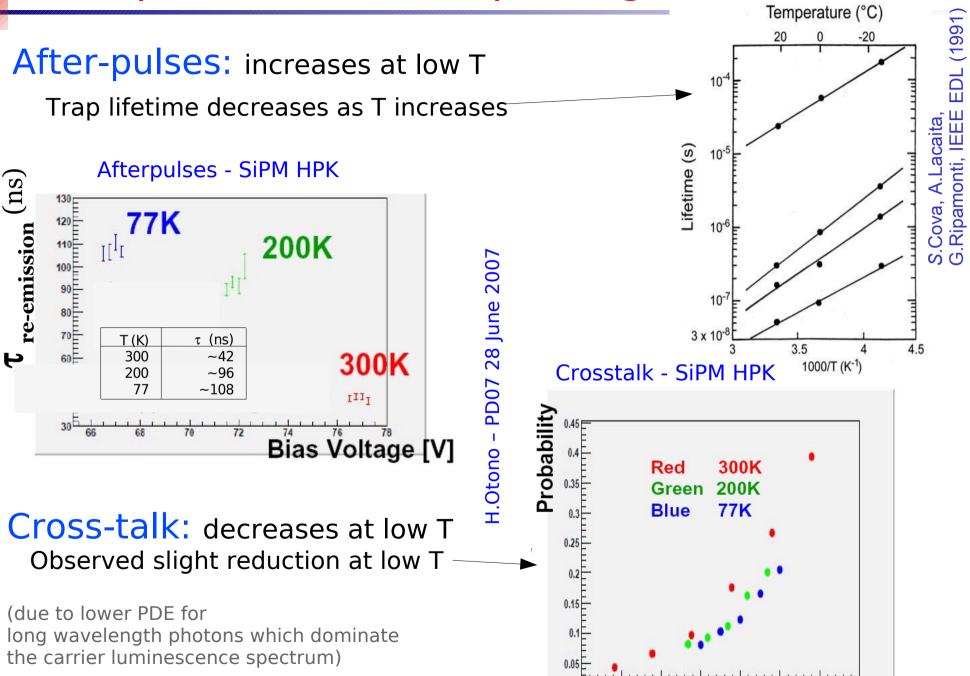


### Counteract:

- optical isolation between cells by trenches filled with opaque material
- low over-voltage operation helps



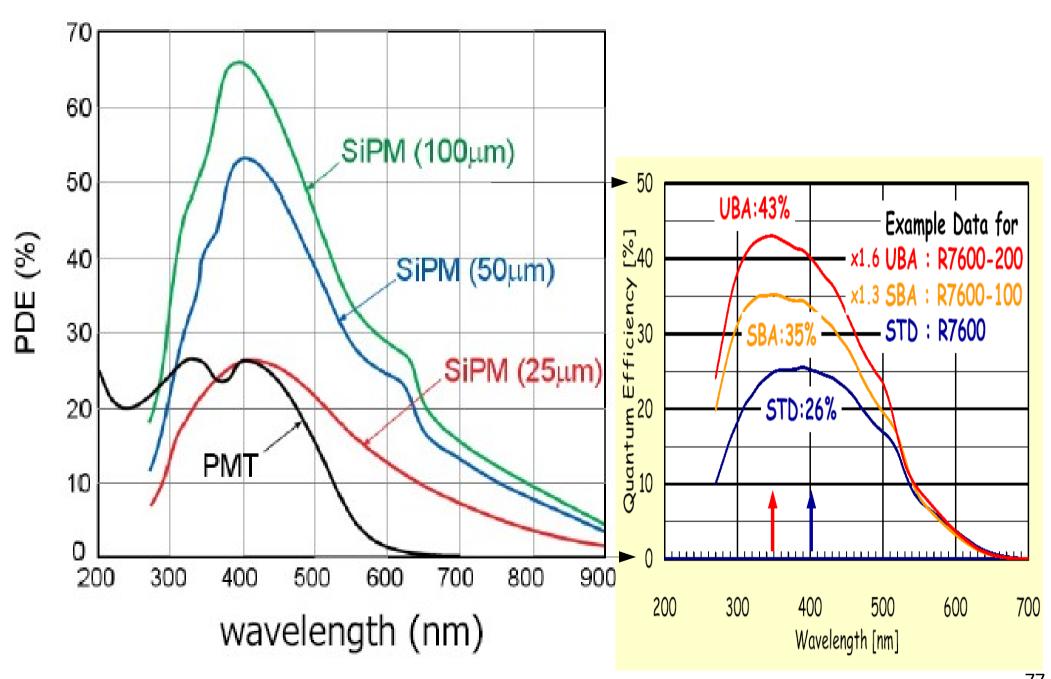
# T dependence: after-pulsing, cross-talk



Over Voltage [V]



# Hamamatsu: PDE of SiPM vs QE of PMT



# Comparison HPK-IRST

| Product.    | Hamamatsu                         |              | IRST                              |              |
|-------------|-----------------------------------|--------------|-----------------------------------|--------------|
| Type        | n+ n- epi n-substrate             | el.<br>holes | n+ p+ p- epi p-substrate          | holes<br>el. |
| Gain        | 10 <sup>5</sup> - 10 <sup>6</sup> |              | 10 <sup>5</sup> - 10 <sup>6</sup> |              |
| PDE         | 30-70%<br>(UV)-blue-green         |              | 30-70%<br>(blue)-green-IR         |              |
| Noise       | 200kHz - 1MHz                     |              | ~ HPK x 2                         |              |
| After-pulse | ~ 10%                             |              | ~ 1%                              |              |
| Cross-talk  | ~ 10%                             |              | ~ 1%                              |              |
| Timing      | ~ 100 ps                          |              | ~ 60 ps                           |              |

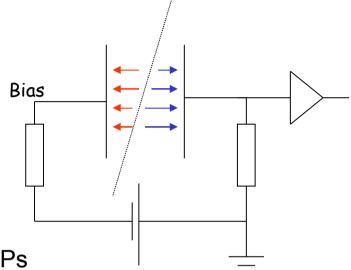
# Fast detectors, fast signals

### **Detector Signals:**

Moving charges (in an electric field):

$$i(t)= n(t) q v(t)$$

Rise-time i'(t)= q [ n(t) v'(t) + n'(t) v(t)]



### Maximize

n electron multiplication PMTs, MCPsdv/dt qE/m electric field (in vacuum)

dn/dt primary ionisation, multiplication

v t . qE /m electric field

- Vacuum devices
- Electron multiplication
- Low capacitance
- High electric fields

# Fast detectors

Sub-nanosecond: 10-100 ps rise-time

### Fast

|             |                      | Signals           | Rise-time Tim | ne resolution |  |  |
|-------------|----------------------|-------------------|---------------|---------------|--|--|
| Solid state |                      |                   |               |               |  |  |
| •           | APDs                 | 10 <sup>2</sup>   | 300 ps        | 50 ps         |  |  |
| •           | Silicon PMs          | 10 <sup>7</sup>   | 100 ps        | 50 ps         |  |  |
| •           | 3D Silicon           | 104               | 500ps         | ?             |  |  |
| Very fast   |                      |                   |               |               |  |  |
| •           | Multi-anode/mesh PM7 | s 10 <sup>7</sup> | 200ps         | 50 ps         |  |  |
| •           | MCP PMTs             | 10 <sup>6</sup>   | 150 ps        | 20-30 ps      |  |  |
| •           | Multi anodes MCP PM  | Ts                | 30 ps?        | 1 ps?         |  |  |

# Pulse sampling

### Digitize samples over pedestal and signal

Fast analog sampler + ADC: [E. Delagnes, Saclay, this workshop]

Assuming the signal waveform is known from the detector and electronics properties:

Least square fit yields:

- Amplitude
- Time

Iterate with new values until convergence

LSQF: [W.E. Cleland and E.G. Stern. NIM A 338 pp 467-497]

- All samples contribute to timing estimation
- Very robust to noise